Overview

HP Z6 G4 Workstation



Front view

- 1. Integrated Front Handle
- 2. Front I/O module options
 - Premium (optional, shown here): power button, 2 USB 3.1 G1 Type-A, 2 USB 3.1 G2 Type-C[™] (Left-most Type A port has charging capability), Headset/Mic, Media Card Reader (optional).
 - Standard: power button, 4 USB 3.1 G1 Type-A (left-most Type A port has charging capability), Headset/Mic, Media Card Reader (optional).
- 3. 2 x 5.25" external bays
- 4. 1 Slim ODD bay



Overview



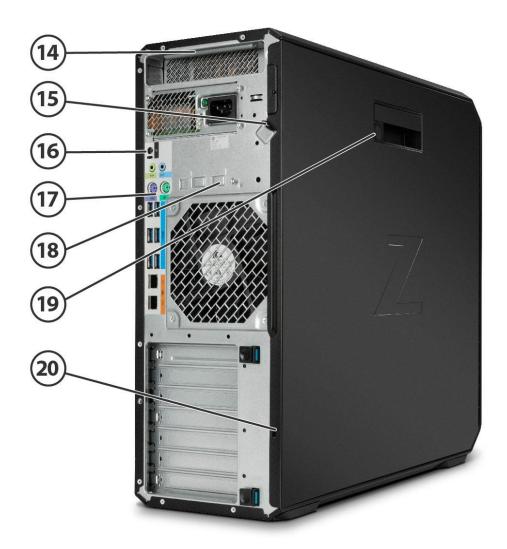
Internal view

- 5. Power supply: 1000W 90% efficient with 2 graphics power adapters
- 6. 6 DIMM slots: DDR4-2666 Registered RAM
- 7. Intel® Xeon® processor Scalable family
- 8. 2nd CPU & memory riser connector: adds 2nd CPU socket and (6) DIMM slots
- 9. PCIe slots: 2 PCIe G3 x16, 3 PCIe G3 x4, 1 PCIe G3 x8

- 10. 6 x 6Gb/s SATA ports
- 11. 2 PCle G3 x4 M.2 for SSDs
- 12. 2 x 2.5"/3.5" internal drive bays
- 13. 2 x 5.25" external drive bays



Overview



- 14. Rear handle
- 15. Padlock loop
- 16. Rear power button
- 17. Rear I/O (top to bottom): audio in/out, keyboard/mouse PS/2, 6 USB 3.1 G1 Type-A, 2 x 1GbE LAN ports

Rear view

- 18. HP Dual Port 10GBase-T NIC module slot (optional)
- 19. Side panel barrel keylock (optional)
- 20. Kensington lock slot

Overview

Overview

Form Factor
Operating Systems

Minitower Preinstalled:

- Windows 10 Pro 64 for Workstations
- Windows 10 Downgrade to Windows 7
- HP Linux-ready (minimal OS ready for customer OS installation)
- Red Hat® Enterprise Linux® Desktop Workstation (Paper license with 1 year support; no preinstalled OS)

Supported:

- Windows 7 Professional 64-bit (downgrade media available by request from HP Support)*
- Red Hat Enterprise Linux Desktop 7.4
- SUSE Linux Enterprise Desktop 12 SP3
- Ubuntu 16.04 LTS

Notes: For detailed Linux® OS/hardware support information, see: http://www.hp.com/support/linux_hardware_matrix

*Windows 10 is preinstalled. Windows 7 media is only available upon request from HP Customer Support. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version.

For detailed Windows 7 OS hardware support information see http://h10032.www1.hp.com/ctg/Manual/c05857891.pdf.

Available Processors

Name	Cores	Clock Speed (GHz)	Cache (MB)	Memory Speed (MT/s)	Hyper- Threading	Featuring Intel® vPro™ Technology	Intel® Turbo Boost Technology¹	TDP (W)
Intel® Xeon® Platinum 8180 processor	28	2.5	38.50	2666	YES	YES	3.2, 3.8	205
Intel® Xeon® Platinum 8160 processor	24	2.1	33.00	2666	YES	YES	2.8, 3.7	150
Intel® Xeon® Gold 6152 processor	22	2.1	30.25	2666	YES	YES	2.8, 3.7	140
Intel® Xeon® Gold 6154 processor	18	3.0	24.75	2666	YES	YES	3.7, 3.7	200
Intel® Xeon® Gold 6148 processor	20	2.4	27.50	2666	YES	YES	3.1, 3.7	150
Intel® Xeon® Gold 6146 processor	12	3.2GHz	24.75	2666	YES	YES	YES	165
Intel® Xeon® Gold 6144 processor	8	3.5GHz	24.75	2666	YES	YES	YES	150
Intel® Xeon® Gold 6142 processor	16	2.6	22.00	2666	YES	YES	3.3, 3.7	150
Intel® Xeon® Gold 6140 processor	18	2.3	24.75	2666	YES	YES	3.0, 3.7	140
Intel® Xeon® Gold 6138 processor	20	2.0	27.5	2666	YES	YES	YES	125
Intel® Xeon® Gold 6136 processor	12	3.0	24.75	2666	YES	YES	3.6, 3.7	150
Intel® Xeon® Gold 6134 processor	8	3.2	24.75	2666	YES	YES	3.7, 3.7	130



Overview

14	2.6	19.25	2666	YES	YES	3.3, 3.7	140
16	2.1	22.00	2666	YES	YES	2.8, 3.7	125
6	3.4	19.25	2666	YES	YES	3.7, 3.7	115
14	2.2	19.25	2400	YES	YES	2.6, 3.2	105
12	2.3	16.50	2400	YES	YES	2.7, 3.2	105
10	2.4	13.75	2400	YES	YES	YES	85
4	3.6	16.50	2666	YES	YES	3.7, 3.7	105
12	2.1	16.50	2400	YES	YES	2.4, 3.0	85
10	2.2	13.75	2400	YES	YES	2.5, 3.0	85
4	2.6	8.25	2400	YES	YES	2.9, 3.0	85
8	2.1GHz	11.00	2400	YES	YES	YES	85
8	1.8	11.00	2400	YES	YES	2.1, 3.0	85
8	1.7	11.00	2133	NO	YES	N/A	85
6	1.7	8.25	2133	NO	YES	N/A	85
	16 6 14 12 10 4 12 10 4 8 8	16 2.1 6 3.4 14 2.2 12 2.3 10 2.4 4 3.6 12 2.1 10 2.2 4 2.6 8 2.1GHz 8 1.8	16 2.1 22.00 6 3.4 19.25 14 2.2 19.25 12 2.3 16.50 10 2.4 13.75 4 3.6 16.50 12 2.1 16.50 10 2.2 13.75 4 2.6 8.25 8 2.1GHz 11.00 8 1.8 11.00	16 2.1 22.00 2666 6 3.4 19.25 2666 14 2.2 19.25 2400 12 2.3 16.50 2400 10 2.4 13.75 2400 4 3.6 16.50 2666 12 2.1 16.50 2400 10 2.2 13.75 2400 4 2.6 8.25 2400 8 2.1GHz 11.00 2400 8 1.8 11.00 2400	16 2.1 22.00 2666 YES 6 3.4 19.25 2666 YES 14 2.2 19.25 2400 YES 12 2.3 16.50 2400 YES 10 2.4 13.75 2400 YES 4 3.6 16.50 2666 YES 12 2.1 16.50 2400 YES 10 2.2 13.75 2400 YES 4 2.6 8.25 2400 YES 8 2.1GHz 11.00 2400 YES 8 1.8 11.00 2400 YES	16 2.1 22.00 2666 YES YES 6 3.4 19.25 2666 YES YES 14 2.2 19.25 2400 YES YES 12 2.3 16.50 2400 YES YES 10 2.4 13.75 2400 YES YES 4 3.6 16.50 2666 YES YES 12 2.1 16.50 2400 YES YES 10 2.2 13.75 2400 YES YES 4 2.6 8.25 2400 YES YES 8 2.1GHz 11.00 2400 YES YES 8 1.8 11.00 2400 YES YES	16 2.1 22.00 2666 YES YES 2.8, 3.7 6 3.4 19.25 2666 YES YES 3.7, 3.7 14 2.2 19.25 2400 YES YES 2.6, 3.2 12 2.3 16.50 2400 YES YES 2.7, 3.2 10 2.4 13.75 2400 YES YES YES 4 3.6 16.50 2666 YES YES 3.7, 3.7 12 2.1 16.50 2400 YES YES 2.4, 3.0 10 2.2 13.75 2400 YES YES 2.5, 3.0 4 2.6 8.25 2400 YES YES 2.9, 3.0 8 2.1GHz 11.00 2400 YES YES YES 8 1.8 11.00 2400 YES YES 2.1, 3.0

¹The specifications shown in this column represent the following: (all core maximum turbo frequency, one core maximum turbo frequency). Processors that do not have turbo functionality are denoted as N/A.

Available Processors

Disclaimers

Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Color Black

Convertibility No

Expansion Slots (see more details)

Slot 0:

system board section for Mechanical-only, for use with devices that require only rear bulkhead mounting or when 2nd CPU riser is installed

PCI Express Gen3 x4 - CPU with open-ended connector*

Slot 2:

PCI Express Gen3 x16 - CPU



Overview

Slot 3:

PCI Express Gen3 x4 - PCH with open-ended connector*

Slot 4:

PCI Express Gen3 x8 - CPU with open-ended connector (slot converts to x4 electrical when SSD is installed in 2nd M.2 slot)*

Slot 5:

PCI Express Gen3 x16 - CPU

Slot 6:

PCI Express Gen3 x4 - PCH with open-ended connector*

M.2 PCIe Gen 3 x4 - CPU up to 80mm storage devices

M.2 Slot 2:

M.2 PCIe Gen 3 x4 - CPU up to 80mm storage devices

* Open-ended connector allows a greater bandwidth (e.g. x16) card to be installed physically into a lower bandwidth connector/slot.

Expansion Bays (see storage section for more 2 external 5.25" bays details)

2 internal 3.5" bays (with acoustic dampening rail assemblies pre-installed)

- 3rd and 4th 3.5" HDD each occupy one external bay
- 3rd and 4th 2.5" HDD/SSD occupy a single external bay within a 2:1 carrier)

1 dedicated 9.5mm slim optical disk drive bay

Front I/O

- Base: Power button, 1 Headset audio port, 4 USB 3.1 G1 Type A (1 charging)
- Premium (optional): Power button, 1 Headset audio port, 2 USB 3.1 G2 Type C™, 2 USB 3.1 G1 Type A (1 charging)
- Optional: SD reader

Internal I/O

1 USB 3.1 G1 (aka USB 3.0) single-port header, 1 USB 2.0 single-port header and 1 USB 2.0 dual-port

header

Rear I/O

6 USB 3.1 G1 (aka USB 3.0) Type A ports, 2 1Gbe LAN ports (1x supporting Intel® AMT), Audio: 1 Line out, 1 Line in (Line in can be retasked as microphone), 1 PS/2 mouse port, 1 PS/2 keyboard port, 1

Rear power button

Optional: 1 serial port (cable up to rear bulkhead)

Interfaces Supported

SD card reader (optional)

6-channel SATA interface (6 @ 6.0 Gb/s)

6 channels are eSATA configurable for use with eSATA CTO/AMO Kit (No hot plug / hot swap

supported)

USB 2.0, USB 3.1 G1 (aka USB 3.0), USB 3.1 G2 (optional)

On-board RAID Support

SATA RAID 0 Striped Array Configuration SATA RAID 1 Mirrored Array Configuration SATA RAID 10 Striped/Mirrored Configuration

Chassis Dimensions (H x H: 17.5" (445mm)

WxD)

W: 6.65" (169mm) D: 18.3" (465mm)



Overview

Packaged Dimensions H: 24" (610mm)

W: 12.3" (313mm) D: 23.3" (593mm)

Rack Dimensions 4U

Weight Exact weights depend upon configuration (System weight only).

Minimum: 13.1 kg (29 lbs.) Standard: 13.6 kg (30.1 lbs.) Maximum: 23.9 kg (52.7 lbs.)

Temperature Operating: 5° to 35°C (40° to 95°F)

Non-operating: -40° to 60°C (-40° to 140°F)

Note: Above 1524 m (5,000 feet) altitude, maximum operating temperature is reduced by 1°C (1.8°F)

per 305 m (1,000 feet) elevation increase

Humidity Operating: 10% to 85% relative humidity, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90% relative humidity, non-condensing, 35° C maximum wet bulb

Maximum Altitude (non-

pressurized)

Operating: 3,048m (10,000ft) Non-operating: 9,144m (30,000ft)

Note: Above 1524 m (5,000 feet) altitude, maximum operating temperature is reduced by 1° C (1.8° F)

per 305 m (1,000 feet) elevation increase

Power Supply 1000 watts wide-ranging, active Power Factor Correction, 90% Efficient, with 2X 6-pin graphics power

cables (graphics power cables are 6/8-pin convertible)

The Z6 G4 1000W power supply efficiency report can be found at this link:

https://plugloadsolutions.com/psu_reports/HP_D15-1K0P1A_1000W_ECOS%204838_Report.pdf

Workstation ISV

See the latest list of certifications at

Certifications http://www8.hp.com/us/en/campaigns/workstations/industries-and-partners.html



Supported Components

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Xeon® Scalable CPU				
	Intel® Xeon® Platinum 8180 processor	Υ	N	2DL53AV	
	Intel® Xeon® Platinum 8160 processor	Υ	Υ	2DL51AV	
	Intel® Xeon® Gold 6152 processor	Υ	Υ	2DL48AV	
	Intel® Xeon® Gold 6154 processor	Υ	N	2DL50AV	
	Intel® Xeon® Gold 6148 processor	Υ	Υ	2DL46AV	
	Intel® Xeon® Gold 6146 processor	Υ	Υ	2SQ66AV	
	Intel® Xeon® Gold 6144 processor	Υ	Υ	2SQ65AV	
	Intel® Xeon® Gold 6142 processor	Υ	Υ	2DL44AV	
	Intel® Xeon® Gold 6140 processor	Υ	Υ	2DL42AV	
	Intel® Xeon® Gold 6138 processor	Υ	Υ	3JN82AV	
	Intel® Xeon® Gold 6136 processor	Υ	Υ	2DL40AV	
	Intel® Xeon® Gold 6134 processor	Υ	Υ	2DL38AV	
	Intel® Xeon® Gold 6132 processor	Υ	Υ	2DL36AV	
	Intel® Xeon® Gold 6130 processor	Υ	Υ	2DL34AV	
	Intel® Xeon® Gold 6128 processor	Υ	Υ	2DL32AV	
	Intel® Xeon® Gold 5120 processor	Υ	Υ	2DL28AV	
	Intel® Xeon® Gold 5118 processor	Υ	Υ	2DL26AV	
	Intel® Xeon® Gold 5115 processor	Υ	Υ	4NA01AV	
	Intel® Xeon® Gold 5122 processor	Υ	Υ	2DL30AV	
	Intel® Xeon® Silver 4116 processor	Υ	Υ	2DL24AV	
	Intel® Xeon® Silver 4114 processor	Υ	Υ	2DL22AV	
	Intel® Xeon® Silver 4112 processor	Υ	Υ	2DL20AV	
	Intel® Xeon® Silver 4110 processor	Υ	Υ	3JN81AV	
	Intel® Xeon® Silver 4108 processor	Υ	Υ	2DL18AV	
	Intel® Xeon® Bronze 3106 processor	Υ	Υ	2DL16AV	
	Intel® Xeon® Bronze 3104 processor	Υ	Υ	2DL14AV	

*Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing system required. Performance will vary depending on your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Monitors / Displays		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Z Display Z22n G2		Υ	1JS05AA	
	HP Z Display Z23n G2		Υ	1JS06AA	
	HP Z Display Z24i G2		Υ	1JS08AA	
	HP Z Display Z24n G2		Υ	1JS09AA	
	HP Z Display Z24nf G2		Υ	1JS07AA	
	HP Z Display Z27n G2		Υ	1JS10AA	



Supported Components

HP Z Display Z27s (4K display)

Y J3G07AA

Supported by all operating systems available from HP Screen size measured diagonally

Storage / Hard Drives

SAS Hard Drives				Option	
	SAS Hard Drives for HP Workstations	Factory Configured	Option Kit	Kit Part Number	Support Notes
	HP 300GB 15k SAS SFF	Υ	Υ	L5B74AA	
	NOTE: SAS controller add-in card required				

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SATA (Serial ATA) Hard Drives for HP Workstations				
	500GB SATA 7200RPM 6Gb/s 3.5" HDD	Υ	Υ	LQ036AA	
	500GB SATA 7200RPM 6Gb/s OPAL2 SFF 3.5" HDD	Υ	Υ	D8N29AA	
	1TB SATA 7200RPM 3.5" HDD	Υ	Υ	LQ037AA	
	1TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	WOR10AA	
	2TB SATA 7200RPM HDD	Υ	Υ	QB576AA	
	4TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	K4T76AA	
	NOTES:				

Up to (4) 3.5-inch 7200 rpm SATA drives: 500 GB, 1.0, 2.0, 4.0 TB; maximum system HDD storage: 16.0TB

Supported Components

SATA Solid State Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Solid State Drives (SSDs) for Workstations				
	HP 256GB SATA SSD	Υ	Υ	A3D26AA	
	HP 512GB SATA SSD	Υ	Υ	D8F30AA	
	HP 1TB SATA SSD	Υ	Υ	F3C96AA	
	HP 2TB SATA SSD	Υ	Υ	Y6P08AA	
	HP 256GB SATA SED OPAL2 SSD	Υ	Υ	G7U67AA	
	HP 512GB SATA SED OPAL2 SSD	Υ	Υ	N8T26AA	
	HP 240GB SATA Enterprise SSD	Υ	Υ	T3U07AA	
	HP 480GB SATA Enterprise SSD	Υ	Υ	T3U08AA	

PCIe Solid State Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	PCIe SSDs for HP Workstations				
	HP Z Turbo Drive 256GB MLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD56AA	
	HP Z Turbo Drive 512GB MLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD57AA/AT	
	HP Z Turbo Drive 1TB MLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD58AA	
	HP Z Turbo Drive 256GB TLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD59AA/AT	
	HP Z Turbo Drive 512GB TLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD60AA	
	HP Z Turbo Drive 1TB TLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD61AA	
	HP Z Turbo Drive 256GB Z4/Z6 G4 SED Kit	Υ	Υ	2SA31AA	
	HP Z Turbo Drive 512GB Z4/Z6 G4 SED Kit	Υ	Υ	2SA32AA	
	HP Z Turbo Drive Quad Pro				
	HP Z Turbo Drive Quad Pro 2x256GB PCIe SSD	Υ	Υ	N2M98AA	1
	HP Z Turbo Drive Quad Pro 2x512GB PCIe SSD	Υ	Υ	N2M99AA	1
	HP Z Turbo Drive Quad Pro 2x1TB PCIe SSD	Υ	Υ	T9H99AA	1
	HP Z Turbo Drive Quad Pro 256GB SSD module	N	Υ	N2N00AA	2
	HP Z Turbo Drive Quad Pro 512GB SSD module	N	Υ	N2N01AA	2
	HP Z Turbo Drive Quad Pro 1TB SSD module	N	Υ	T9J00AA	2

Note 1: Dual M.2 SSD modules plus carrier

Note 2: M.2 SSD module only, designed to be installed into Quad Pro carrier

Hard Drive Controllers		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SAS Controller				
	MicroSemi SmartHBA2100-4i4e SAS Controller	Υ	Υ	1FV90AA	
	Microsemi 3152-8i SAS ROC RAID Controller	Υ	Υ	1FV89AA	



Supported Components

Graphics

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes	Supported # of cards
Graphics Cable Adapters					
HP DisplayPort to VGA Adapter	Υ	Υ	AS615AA		
HP DisplayPort to HDMI Adapter	Υ	Υ	K2K92AA		
HP DisplayPort to Dual Link DVI Adapter	Υ	Υ	NR078AA		1
HP DisplayPort to DVI-D Adapter	Υ	Υ	FH973AA		1
HP DisplayPort to DVI-D Adapter (2-pack)	Υ	N			1
HP DisplayPort to DVI-D Adapter (4-pack)	Υ	N			1
HP DisplayPort to DVI-D Adapter (6-pack)	Υ	N			1
NVIDIA® SLI 3-slot Graphics Connector	Υ	Υ	2YY85AA		1
Entry 3D					
NVIDIA® Quadro® P400 1st GFX 2GB Graphics	Υ	Υ	1ME43AA/AT		2
NVIDIA® Quadro® P600 1st GFX 2GB Graphics	Υ	Υ	1ME42AA/AT		2
AMD FirePro™ W2100 2GB Graphics	Υ	Υ	J3G91AA/AT		2
Mid-range 3D					
NVIDIA® Quadro® P1000 1st GFX 4GB Graphics	Υ	Υ	1ME01AA/AT		2
NVIDIA® Quadro® P2000 1st GFX 5GB Graphics	Υ	Υ	1ME41AA/AT		2
AMD Radeon™ Pro WX 3100 4GB Graphics	Υ	Υ	2TF08AA		2
AMD Radeon™ Pro WX 4100 4GB Graphics	N	Υ	ZOB15AA/AT		2
High End 3D					
NVIDIA® Quadro® P4000 1st GFX 8GB Graphics	Υ	Υ	1ME40AA/AT		2
NVIDIA® Quadro® P5000 1st GFX 16GB Graphics	Υ	Υ	ZOB13AA/AT		2
NVIDIA® Quadro® P6000 1st GFX 24GB Graphics	Υ	Υ	ZOB12AA/AT		1
AMD Radeon™ Pro WX 7100 1st GFX 8GB Graphics	Υ	Υ	ZOB14AA/AT		2

NOTE: NVIDIA® Quadro® GP100 and AMD Radeon™ Pro WX 9100 support available the first half of 2018

Memory	СТО	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	DDR4-2666 ECC Registered DIMMs				
	8GB (1x8GB) DDR4-2666 ECC Reg 1CPU Memory	Υ	Υ	1XD84AA/AT	
	16GB (2x8GB) DDR4-2666 ECC Reg 1CPU Memory	Υ			
	24GB (3x8GB) DDR4-2666 ECC Reg 1CPU Memory	Υ			
	32GB (4x8GB) DDR4-2666 ECC Reg 1CPU Memory	Υ			
	48GB (6x8GB) DDR4-2666 ECC Reg 1CPU Memory	Υ			
	16GB (1x16GB) DDR4-2666 ECC Reg 1CPU Memory	N	Υ	1XD85AA/AT	
	32GB (2x16GB) DDR4-2666 ECC Reg 1CPU Memory	Υ			
	48GB (3x16GB) DDR4-2666 ECC Reg 1CPU Memory	Υ			
	64GB (4x16GB) DDR4-2666 ECC Reg 1CPU Memory	Υ			
	96GB (6x16GB) DDR4-2666 ECC Reg 1CPU Memory	Υ			



Supported Components

32GB (1x32GB) DDR4-2666 ECC Reg 1CPU Memory	N	Υ	1XD86AA/AT
64GB (2x32GB) DDR4-2666 ECC Reg 1CPU Memory	Υ		
96GB (3x32GB) DDR4-2666 ECC Reg 1CPU Memory	Υ		
128GB (4x32GB) DDR4-2666 ECC Reg 1CPU Memory	Υ		
192GB (6x32GB) DDR4-2666 ECC Reg 1CPU Memory	Υ		
32GB (4x8GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
48GB (6x8GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
64GB (8x8GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
96GB (12x8GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
64GB (4x16GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
96GB (6x16GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
128GB (8x16GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
192GB (12x16GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
128GB (4x32GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
192GB (6x32GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
256GB (8x32GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		
384GB (12x32GB) DDR4-2666 ECC Reg 2CPU Memory	Υ		

NOTES:

For details on the supported memory configurations on the HP Z6 G4 Workstation, please refer to the System Technical Specifications - System Board section of this document.

Each processor supports up to 6 channels of DDR4 memory. To realize full performance at least 1 DIMM must be inserted into each channel.

With single-processor configurations, 6 DIMM slots are available. 6 additional DIMM slots are available with the 2nd CPU & Memory Module.

The CPUs determine the speed at which the memory is clocked. If a 2400MT/s capable CPU is used in the system, the maximum speed the memory will run at is 2400MT/s, regardless of the specified speed of the memory.

ONLY registered DDR4 DIMMs are supported. DDR3 DIMMs ARE NOT SUPPORTED.

NOTE 2: Z6 G4 configurations that include a 2nd CPU require the HP Z6 Memory Cooling Solution, which is available both CTO (2JA81AV) and AMO (2HW44AA). Z6 G4 configurations that include greater than 32GB total system memory require the HP Z6 Memory Cooling Solution, which is available both CTO (2JA81AV) and AMO (2HW44AA).

Multimedia and Audio Devices



Supported Components

Multimedia and Audio Devices

	Factory	Option	Kit Part	Support
	Configured	Kit	Number	Notes
Integrated Realtek HD ALC221 Audio	Υ	N		

Optical and Removable Storage

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP SlimTray Optical Drives	comiguica	option kit	Number	Hotes
HP 9.5mm Slim Blu Ray Disc Writer	Υ	Υ	K3R65AA	
HP 9.5mm Slim DVD ROM	Υ	Υ	K3R63AA	
HP 9.5mm Slim DVD Writer	Υ	Υ	K3R64AA	
HP SD Card Reader				
HP SD 4 Card Reader	Υ	Υ	YOL99AA	

Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

With Blu-ray, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

Networking and Communications

	Factory Configured	Option Kit	Kit Part Number	Support Notes
HP i350-T2 PCIe Dual Port Gigabit NIC	Υ	Υ	V4A91AA	
Intel® i350-T4 PCIe 4-Port Gigabit NIC	N	Υ	W8X25AA	
Intel® Ethernet I210-T1 PCIe x1 Gb NIC	Υ	Υ	E0X95AA	
HP Dual Port 10GBase-T NIC Module	Υ	Υ	1QL49AA	
Intel® 8265 802.11 a/b/g/n/ac + BT PCIe WLAN	N	Υ	1QL48AA	
Intel® X550-T2 10GbE Dual Port NIC	Υ	Υ	1QL46AA	
Intel® X710-DA2 10GbE SFP+ Dual Port NIC	Υ	Υ	1QL47AA	1
HP 10GbE SFP+ SR Transceiver	Υ	Υ	C3N53AA	

Note 1: Windows 7 is NOT supported

Racking and Physical Security



Supported Components

Racking and Physical Security

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes	
HP Z4/Z6 Side Panel Barrel Keylock	Υ	N			
HP Solenoid Lock / Hood Sensor	Υ	N			
HP Z4/Z6 Depth Adjustable Fixed Rail Rack Kit	N	Υ	2HW42AA		
HP Keyed Cable Lock 10mm	N	Υ	T1A62AA		

Input Devices

			Option Kit	
	Factory Configured	Option Kit	Part Number	Support Notes
HP Wireless Business Slim Keyboard and Mouse	Υ	Υ	N3R88AA	
Business Slim PS/2 Wired Keyboard	Υ	Υ	N3R86AA	
USB Business Slim Wired Keyboard	Υ	Υ	N3R87AA	
USB Premium Wired Keyboard	Υ	Υ	Z9N40AA	
USB Wired SmartCard CCID Keyboard	Υ	Υ	E6D77AA	
3Dconnexion CADMouse	Υ	Υ	M5C35AA	
HP Optical USB Mouse	Υ	Υ	QY777AA	
HP PS/2 Mouse	Υ	Υ	QY775AA	
HP USB Hardened Mouse	Υ	Υ	P1N77AA	

Other Hardware

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP ENERGY STAR® Certified Configuration	Υ			
HP Z Premium Front I/O 2xUSB-A 2xUSB-C	Υ	Υ	1XM32AA	
HP Z6 G4 Memory Cooling Solution	Υ	Υ	2HW44AA	Note 1
HP Internal USB Port Kit	N	Υ	EM165AA	Note 2
HP eSATA 2 port PCI Bulkhead Kit	Υ	Υ	GM110AA	
HP Serial Port Adapter	Υ	Υ	PA716A	
HP Workstation Mouse Pad	Υ			

Note 1: Z6 G4 configurations that include a 2nd CPU require the HP Z6 Memory Cooling Solution, which is available both CTO (2JA81AV) and AMO (2HW44AA). Z6 G4 configurations that include greater than 32GB total system memory require the HP Z6 Memory Cooling Solution, which is available both CTO (2JA81AV) and AMO (2HW44AA).

Note 2: The HP Internal USB Port kit has a single USB 2.0 type A connector.

Software				Option Kit	
		Factory Configured	Option Kit	Part Number	Support Notes
	Sobey Video Editing SW	Y	N		



Supported Components

SW HP RGS for Z

Υ

N



Supported Components

Operating Systems

Support Notes

Windows 10 Pro 64

Windows 7 Professional 64-bit Note 3, 4

Windows 10 Downgrade to Windows 7

HP Linux® Installer Kit

Note 2

Red Hat® Enterprise Linux® (RHEL) Workstation - Paper License (1yr)

Note 1

NOTE 1: This second OS must be ordered with the HP Linux® Installer Kit as the first OS.

NOTE 2: includes drivers for 64-bit OS versions of RHEL 6 & 7, SUSE Linux® Enterprise Desktop 11 and Ubuntu 14.04. For detailed Linux® OS/hardware support information, see: http://www.hp.com/support/linux_hardware_matrix

NOTE 3: downgrade media available by request from HP Support. For detailed Windows 7 OS hardware support information see http://h10032.www1.hp.com/ctg/Manual/c05857891.pdf.

NOTE 4: Windows 10 is preinstalled. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version



System Board

System Board Form Main System Board: **Factor** 24 x 31 cm

9.6 x 12.2 inches

2nd CPU/Memory Board (optional):

14.9 x 29.2 cm 5.85 x 11.50 inches

Processor Socket FCLGA3647 (Socket P)

1st CPU on system board

2nd CPU on optional 2nd CPU/Memory Module UPI: Up to 10.4GT/second, depending on processor

CPU Bus Speed Chipset Intel® C622 Chipset Super I/O Controller **Nuvoton SIO15**

Memory Expansion

Slots

6 on system board(CPU0) + 6 on optional 2nd CPU/Memory Module(CPU1)

Memory Type Supported

DDR4, RDIMM (Registered), ECC: 8GB, 16GB and 32GB

Memory Modes Memory Speed

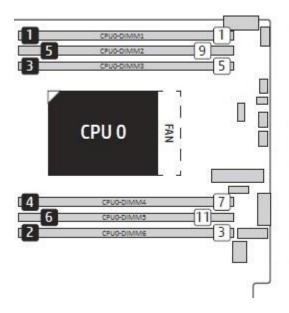
NUMA (Non-Uniform Memory Architecture), Memory Node Interleave

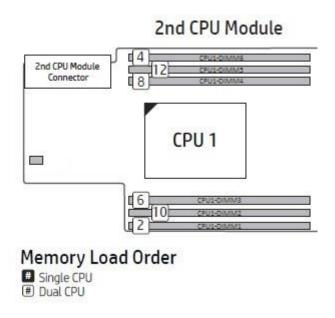
Supported

2133MT/s, 2400MHz and 2666MT/s

Memory Loading Order:

Load Order for Single and Dual Processor Configuration





Maximum Memory

Supports up to 384GB with two processors.



System Technical Specifications

Memory Configuration (Supported)

- Only Registered ECC DIMMs are supported.
- Do not install memory modules into memory slots if corresponding processor is not installed.
- Dual processor configurations with memory modules installed for only one processor is not supported.

Notes

For systems installed with Microsoft Windows 7 (Ultimate, Enterprise or Pro), the maximum accessible system memory is 192GB

PCI Express Connectors Slot 0:

Mechanical-only, for use with devices that require only rear bulkhead mounting or when 2nd CPU riser is installed

Slot 1:

PCI Express Gen3 x4 - CPU with open-ended connector*

Slot 2:

PCI Express Gen3 x16 - CPU

Slot 3:

PCI Express Gen3 x4 - PCH with open-ended connector*

PCI Express Gen3 x8 - CPU with open-ended connector (slot converts to x4 electrical when SSD is installed in 2nd M.2 slot)*

Slot 5:

PCI Express Gen3 x16 - CPU

PCI Express Gen3 x4 - PCH with open-ended connector*

M.2 Slot 1:

M.2 PCIe Gen 3 x4 - CPU up to 80mm storage devices

M.2 Slot 2:

M.2 PCIe Gen 3 x4 - CPU up to 80mm storage devices

* Open-ended connector allows a greater bandwidth (e.g. x16) card to be installed physically into a lower bandwidth connector/slot.

Supported Drive Interfaces

SATA 6 SATA @6Gb/s, supports RAID 0, 1 and NCQ.

Factory integrated RAID is Microsoft Windows only.

Serial Attached SCSI Requires Optional PCIe card

Factory Configured

RAID

RAID 0 configuration - striped array

RAID 1 configuration - mirrored array

RAID 10 striped and mirrored array

*HW RAID functionality not supported by Linux®. Use SW RAID functionality

provided in the Red Hat® Operating system instead.

Integrated Graphics No

Network Controller Integrated Intel® I219LM GbE LAN



Supports the following management functionalities: Intel® AMT11.2, TXT, DASH

1.1, WOL, VLAN, and PXE 2.1

Integrated Intel X722 for 1GbE Data rates supported: 1000 Mb/s

Compliance IEEE 802.1as/1588v2, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az,

802.3x

Up to 16 UDP/TCP programmable filters

Bus architecture: PCIe 3.0
UEFI and PXE Boot ROM support
Intel iWARP Support (RDMA)
Network transfer rates:

1000BASE-T (full-duplex) 2000 Mb/s

Management capabilities: WOL (Excluding Max Power Savings), auto MDI

crossover, PXE, Quad Hash filtering, RSS, Advanced cable

diagnostics

External SATA (eSATA) Supported on all SATA ports configurable with optional eSATA* cable kit

* hot plug / hot swap not supported with eSATA

USB Connector(s) Front Front USB depends on which FIO module is selected:

- Standard: 4 USB 3.1 G1 Type A (1 charging)

- Premium: 2 USB 3.1 G2 Type C, 2 USB 3.1 G1 Type A (1 charging)

Rear 6 USB 3.1 G1 Type A

Internal 1 USB 3.1 G1 single-port header

1 USB 2.0 single-port header 1x USB 2.0 dual-port header

HD Integrated Audio Realtek ALC221

Flash ROM Yes

CPU Fan Header One for each CPU socket

Rear Chassis Fan Header Yes
Front PCI Fan Header Yes
CMOS Battery Holder - Yes

Lithium

Integrated Trusted Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670)

Platform Module Common Criteria EAL4+ Certified

Convertible to FIPS 140-2 Certified mode through firmware v7.80

TPM Certified products list:

https://trustedcomputinggroup.org/membership/certification/tpm-certified-products/

Power Supply Headers Yes **Power Switch, Power** Yes

LED & Hard Drive LED

Header

Clear Password Jumper Yes

Serial Port 1 internal header

Parallel Port No

Keyboard/Mouse USB or PS/2

Hood Lock Header Yes **Hood Sensor Header** Yes

Memory Fan 1 Memory Fan Header per CPU

AUX IN (audio) No

System Technical Specifications

Z6 Required Power Supply Info

Power Supply1000W 90% Efficient, Custom PSU
(Wide Ranging, Active PFC)

Operating Voltage Range 90–269 VAC

Rated Voltage Range100-127 VAC
200-240 VAC
118 VAC

Rated Line Frequency 50-60 Hz 400 Hz **Operating Line Frequency Range** 47-66 Hz 393-407 Hz

12 A @ 100-127 VAC

Rated Input Current 6.3 A @ 200-240 VAC 12A @ 118 VAC

Heat Dissipation (Configuration and software dependent)Typical = 2467 btu/hr
Maximum = 4112 btu/hr

(Configuration and software dependent)

Power Supply Fan

80x25 mm variable speed

ENERGY STAR® Qualified Yes
(Configuration dependent)

The Z6 G4 1000W power supply efficiency report can be found at this link:

80 PLUS® Compliant

https://plugloadsolutions.com/psu_reports/HP_D15-1K0P1A_1000W_ECOS%204838_Report.pdf

Yes, 90% Efficient

FEMP Standby Power Compliant @115V
(<1W in S5 – Power Off)

EuP Compliant @ 230V
(<0.5 Win C5 – Power Off)

Yes

(<0.5 W in S5 – Power Off)

CECP Compliant @ 220V

(<4W in S3 – Suspend to RAM)

Yes; Configuration dependent

Power Consumption in sleep mode
(as defined by ENERGY STAR®) – Suspend to RAM

(as defined by ENERGY STAR®) – Suspend to RAM
(S3)
(Instantly Available PC)

Built-in Self Test LED

Surge Tolerant Full Ranging Power Supply
(withstands power surges up to 2000V)

Yes

Sensor Header Integrated in Front User Interface (Power Switch, Power LED, HDD LED,

Speaker) Cable

Integrated Gigabit Ethernet Integrated Intel® I-218 Gbit LAN

Clear CMOS Button Yes

System Technical Specifications

System Configuration

Example Z6 G4	Processor	1x Intel Xeon	3104 (Six-core)					
Configuration #1	Memory	1x 8GB DDR4-	-2666 (Register	ed DIMM)				
	Graphics	1x NVIDIA Qua	dro P400					
	Disks / Optical	1x 500GB SAT	A 7200 ; 1x Slin	n DVD-ROM SA	ATA			
	Power Supply	1000W 90% c	ustom PSU					
	Other	NA	IA .					
		115	VAC	230	VAC	100	VAC	
Energy Consumption		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	
	Windows Idle (S0)	54.109		54.	586	54.	906	
	Windows Busy Typ(S0)	94	.256	94.275		94.043		
	Windows Busy Max (S0)	95	.992	95.268		95.643		
	Sleep (S3)	6.219	6.205	6.319	6.306	6.334	6.239	
	Off (S5)	3.354	3.343	3.521	3.341	3.350	3.342	
	Zero Power Mode (ErP)	0.	209	0.388 0.195			95	
		115	5 VAC	230	VAC	100	VAC	
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
(Btu/hr)	Windows Idle (S0)	184	1.619	186	.247	187	.339	
	Windows Busy Typ(S0)	321	1.601	321	.666	320	.875	
	Windows Busy Max (S0)	327	7.524	325	.054	326	.334	
	Sleep (S3)	21.219	21.171	21.561	21.516	21.611	21.287	
	Off (S5)	11.444	11.406	12.014	11.399	11.430	11.403	
	Zero Power Mode (ErP)	0.	713	1.3	323	0.6	65	

Example Z6 G4	Processor	1x Intel Xeon 4108 (Eight-core)						
Configuration #2	Memory	4x 8GB DDR4	-2666 (Registe	red DIMM)				
	Graphics	1x NVIDIA Quadro P2000						
	Disks / Optical	2x 1TB SATA 7	7200 ; 1x Slim D	VDRW SATA				
	Power Supply	1000W 90% custom PSU						
	Other	NA						
Energy Consumption		115	VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	
-	Windows Idle (S0)	61.661 61.531		531	61.354			
	Windows Busy Typ(S0)	168.665 167.375		166	.535			
	Windows Busy Max (S0)	166	166.097 163.682		.682	169.674		
	Sleep (S3)	7.231	7.177	7.229	7.217	7.324	7.248	
	Off (S5)	3.376	3.366	3.527	3.512	3.354	3.350	
	Zero Power Mode (ErP)	0.	211	0.3	886	0.1	95	
		115	5 VAC	230	VAC	100	VAC	
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
(Btu/hr)	Windows Idle (S0)	210).387	209	.944	209	.340	



System Technical Specifications

Windows Busy Typ((S0) 5	575.485 576.959		.084	568.217	
Windows Busy Max	(S0) 5			.543	578	578.928
Sleep (S3)	24.672	24.488	24.665	24.624	24.989	24.730
Off (S5)	11.519	11.484	12.034	11.983	11.443	11.430
Zero Power Mode (I	ErP) (0.720	1.3	317	0.6	65

Example Z6 G4	Processor	1x Intel Xeon	6136 (Twelve-c	ore)				
Configuration #3	Memory	6x 8GB DDR4	-2666 (Register	ed DIMM)				
ENERGY STAR	Graphics	1x NVIDIA Qua	adroP4000					
QUALIFIED	Disks/Optical	2x 1TB SATA	7200 ; 1x Slim D	VDRW SATA				
	Power Supply	1000W 90% c	ustom PSU					
	Other	NA	IA					
Energy Consumption		115	5 VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	
	Windows Idle (S0) 79.074 79.109 79.93					938		
	Windows Busy Typ(S0)	324	1.975	317	.991	327	.451	
	Windows Busy Max (S0)	328	3.268	320.296		329.668		
	Sleep (S3)	7.847	7.756	7.878	7.826	7.931	7.852	
	Off (S5)	3.353	3.348	3.535	3.489	3.373	3.355	
	Zero Power Mode (ErP)	0.	206	0.3	886	0.1	96	
		115	5 VAC	230	VAC	100	VAC	
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
(Btu/hr)	Windows Idle (S0)	269	9.801	269	.920	272	.748	
	Windows Busy Typ(S0)	110	8.815	1084	1.985	1117	'.262	
	Windows Busy Max (S0)	112	0.051	1092	2.850	1124	1.827	
	Sleep (S3)	26.774 26.463 26.880 26.702 27.061						
	Off (S5)	11.441	11.426	12.061	11.904	11.509	11.447	
	Zero Power Mode (ErP)	0.	703	1.3	317	0.6	669	

Example Z6 G4	Processor	2x Intel Xeon 8160 (Dual 24-core)						
Configuration #4	Memory	12x 32GB DDF	R4-2666 (Regi	istered DIMM)				
	Graphics	2x NVIDIA Qua	dro P5000					
	Disks / Optical	4x 2TB SATA 7	200 ; 1x Slim	DVDRW SATA				
	Power Supply	1000W 90% custom PSU						
	Other NA							
Energy Consumption		115	VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	
	Windows Idle (S0)	112.	388	115	5.635 112		.102	
	Windows Busy Typ(S0)	sy Typ(S0) 512.368 490.165						
	Windows Busy Max (S0)	50) 698.548 673.465 706.461						
1	Sleep (S3)	14.208 13.833 14.698 14.487 15.176 13.886						



System Technical Specifications

	Off (S5)	3.511	3.418	3.575	3.570	3.509	3.412
	Zero Power Mode (ErP)	0.2	87	0.3	87	0.2	272
		115	VAC	230	VAC	100	VAC
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
(Btu/hr)	Windows Idle (S0)	383.	469	394	.547	382	.492
	Windows Busy Typ(S0)	1748	.120	1672	2.443	1797	'.800
	Windows Busy Max (S0)	2383	.446	2297	'.863	2410).445
	Sleep (S3)	48.478	47.198	50.150	49.430	51.781	47.379
	Off (S5)	11.980	11.662	12.198	12.181	11.973	11.642
	Zero Power Mode (ErP)	0.9	79	1.321		0.928	

NOTE: Power consumption measurements do not take advantage of the Intel Turbo Boost Technology. As a result, power consumption measurements may be higher.

DECLARED NOISE EMISSIONS

System Configuratio	n
(Entry level)	

Processor Info	Intel® Xeon® Gold 6130 processor 2.1GHz 12C CPU
Memory Info	24GB (3x8GB) DDR4-2666 ECC Memory RDIMMs
Graphics Info	1-NVIDIA® Quadro® P400 2GB
Disks/Optical	1-500GB SATA 7200RPM 3.5" HDD / 1-HP 9.5mm Slim Blu Ray Disc Writer
Power Supply	1000 W

Declared Noise Emissions (in accordance with ISO		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
7779 and ISO 9296)	Idle	3.3	15
	Hard drive Operating (random reads)	3.5	18

System Configuration
(Mid-range)

Processor Info	Intel® Xeon® Platinum 8168 processor 2.7GHz 24C CPU
Memory Info	96GB (6x16GB) DDR4-2666 ECC Memory RDIMMs
Graphics Info	1-NVIDIA® Quadro® P6000 24GB
Disks/Optical	2-4TB 6Gb/s 7200RPM SATA HDD / 1-HP 9.5mm Slim Blu Ray Disc Writer
Power Supply	1000 W

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
	Idle	3.8	23
	Hard drive Operating (random reads)	3.9	23

System Technical Specifications

System Configuration	Processor Info	2-Intel® Xeon® Gold 6136 processor 3.0GHz 12C CPU
(High end)	Memory Info	192GB (12x16GB) DDR4-2666 ECC Memory RDIMMs
	Graphics Info	1-NVIDIA® Quadro® P6000 24GB
	Disks/Optical	2-4TB 6Gb/s 7200RPM SATA HDD / 1-HP 9.5mm Slim Blu Ray Disc Writer
	Power Supply	1000 W

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
	Idle	3.8	23
	Hard drive Operating (random reads)	3.9	24

ENVIRONMENTAL DATA

Environmental Requirements

Temperature Operating: 5° to 35° C (40° to 95° F)

Non-operating: -40° to 60° C (-40° to 140° F)

Humidity Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb

Maximum Altitude Operating: 3,048 m (10,000 feet)

> Above 1524 m (5.000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation

Non-operating: 9,144 m (30,000 feet)

Shock (non-repetitive) Operating: ½-sine: 40g, 2-3ms (~62 cm/sec)

Non-operating: 1/2-sine: 160 cm/s, 2-3ms (~105g)

square: 422 cm/s, 20q

Vibration

Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g2/Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz

Physical Security and Serviceability

Access Panel Tool-less

Includes system board and memory information.

Tool-less, no carrier or rails required **Hard Drives** Tool-less

Optional 5.25" external bay carriers

Expansion Cards Tool-less

Processor Socket 1st socket on main system board. 2nd socket on optional 2nd CPU/Memory Module.

Blue User Touch Points Yes, on primary serviceable components.

Color-coordinated Cables Yes

and Connectors

Optical Drive

System Technical Specifications

Memory Tool-less

System Board Torx T15 screws

2nd CPU/Memory Module: Tool-less

Dual Color Power/Failure LED = Yes Front of Computer LEDs

HDD Activity LED = Yes

Configuration Record SW Yes

Over-Temp Warning on

Yes, at POST screen on reboot

Screen

Restore CD/DVD Set **Dual Function Front** Yes, restores the computer to its original factory shipping image; can be obtained via HP Support.

Yes, also acts as a reset switch when held for 4 seconds.

Power Switch

Padlock Support Yes

Kensington Cable Lock (optional): Prevents entire system theft and system access. 3mm x 7mm slot at **Cable Lock Support**

rear of system

Universal Chassis Clamp

Lock Support

Solenoid Lock and Hood

Sensor

Access Panel Solenoid Lock: Yes (optional). Activated remotely to prevent system entry.

Access Panel Intrusion Sensor: Yes (optional).

Removable Media Write/Boot Control Yes, user can prevent the workstation from writing to or booting from removable media.

Power-On Password Yes, prevents an unauthorized person from booting up the workstation

Yes

Setup Password

Yes, prevents an unauthorized person from changing the workstation configuration

3.3V Aux Power LED on

System PCA

NIC LEDs (integrated) Yes

(Green & Amber)

CPUs and Heatsinks

LED

CPU heatsink removal requires a T-30 Torx screwdriver.

Power Supply Diagnostic Yes

Front Power Button

Yes **Rear Power Button** Yes

Front Power LED Yes, white (normal), red (fault)

Front Hard Drive Activity Yes, white

Front ODD Activity LED Yes on device

Internal Speaker Yes

System/Emergency ROM

Recovers corrupted system BIOS.

Flash Recovery

Cooling Solutions Air cooled forced convection

Power Supply Fans 1 - 80 mm x 80 mm x 25 mm (non-serviceable)

CPU Heatsink Fan 1st CPU: 1 - 80mm

Optional 2nd CPU: 1 - 60mm x 25mm

Front memory fan: 1 - 80mm x 25mm **Memory Fan**

Memory duct blower: 1 - 90mm x 25mm 2nd CPU/Memory Module: 1 - 60mm x 25mm

System Technical Specifications

Chassis Fans Front chassis fan: 1 - 120mm x 25mm

Rear chassis fan: 1 - 120mm x 25mm

HP Vision Diagnostics Offline Edition

HP PC Hardware Diagnostics (UEFI) enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing ESC then F2 upon the PC reboot, and is

available as a download from HP Support.

Access Panel Key Lock ACPI-Ready Hardware

Yes, side panel barrel keylock (optional from the factory only) Advanced Configuration and Power Management Interface (ACPI).

Allows the system to wake from a low-power mode.

Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system

Trusted Platform Module Yes, Infineon TPM 2.0 Certified

Chip

Integrated Chassis

Handles

Yes, Front handle and dedicated rear recess

Power Supply Requires T15 Torx or flat blade screwdriver

PCIe Card Retention Yes, tool-less

Rear (all)

Middle (full-height cards)

Front (full-length cards with extender)

Flash ROM Yes **Diagnostic Power Switch** Yes

LED on board

Clear Password Jumper Yes Clear CMOS Button Yes CMOS Battery Holder Yes

DIMM Connectors Yes

BIOS

BIOS 32-bit Services Standard BIOS 32-bit Service Directory Proposal v0.4

Full BIOS support for PCI Express through industry standard interfaces. **PCI 3.0 Support**

ATAPI ATAPI Removable Media Device BIOS Specification Version 1.0.

BBS BIOS Boot Specification v1.01.

WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is **WMI Support**

fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

BIOS Boot Spec 1.01+

Provides more control over how and from what devices the workstation will boot.

BIOS Power On Users can define a specific date and time for the system to power on.

ROM Based Computer Setup Utility (F10)

Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM Recovers system BIOS in corrupted Flash ROM.

Flash Recovery with

Replicated Setup

Video

Saves BIOS settings to USB flash device in human readable file (HpSetup.txt).

BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed

without entering Computer Configuration Utility (F10 Setup).

SMBIOS System Management BIOS 2.8, for system management information.

Boot Control

Disables the ability to boot from removable media on supported devices.

Memory Change Alert Thermal Alert

Alerts management console if memory is removed or changed.

Monitors the temperature state within the chassis. Three modes:

• NORMAL - normal temperature ranges.

ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid

shutdown or provide for a smoother system shutdown.

• SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash

Provides secure, fail-safe ROM image management from a central network console. Allows the system to enter and resume from low power modes (sleep states).

ACPI (Advanced Management Interface)

Configuration and Power Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.

Supports ACPI 5.0 for full compatibility with 64-bit operating systems.

Ownership Tag

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.

Shutdown

Remote Wakeup/Remote System administrators can power on, restart, and power off a client computer from a remote location.

Instantly Available PC

Allows for very low power consumption with quick resume time.

(Suspend to RAM - ACPI

sleep state S3) **Remote System**

Installation via F12 (PXE 2.1) (Remote Boot from

Allows a new or existing system to boot over the network and download software, including the operating system.

Server)

ROM revision levels Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is

available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

System board revision

level

Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified. Assesses system health at boot time with selectable levels of testing.

Start-up Diagnostics (Power-on Self-Test)

Auto Setup when new hardware installed

System automatically detects addition of new hardware.

Keyboard-less Operation The system can be booted without a keyboard.

Localized ROM Setup

Common BIOS image supports System Configuration Utility (F10 Setup) menus in 14 languages with

local keyboard mappings.

Asset Tag

The user or MIS to set a unique tag string in non-volatile memory.

Per-slot Control **Adaptive Cooling Pre-boot Diagnostics** Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics.

(Pre-video) critical errors are reported via beeps and blinks on the power LED.

Industry Standard Specification Support

Industry Standard Revision Supported by the BIOS

UEFI Specification

2.5

Revision

ACPI Advanced Configuration and Power Management Interface, Version 5.0 ATA (IDE) AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b **CD Boot** "El Torito" Bootable CD-ROM Format Specification Version 1.0

- Enhanced Disk Drive Specification Version 1.1 **EDD**

- BIOS Enhanced Disk Drive Specification Version 3.0

EHCI Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0

PCI PCI Local Bus Specification, Revision 2.3



PCI Power Management Specification, Revision 1.1

PCI Firmware Specification, Revision 3.0, Draft .7

PCI Express PCI Express Base Specification, Revision 2.0

PCI Express Base Specification, Revision 3.0

PMM POST Memory Manager Specification, Version 1.01

SATA Serial ATA Specification, Revision 1.0a

Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0

SPD PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B

TPM Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670)

Common Criteria EAL4+ Certified

Convertible to FIPS 140-2 Certified mode through firmware v7.80

TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

UHCI Universal Host Controller Interface Design Guide, Revision 1.1

USB Universal Serial Bus Revision 1.1 Specification

Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 G1 Specification Universal Serial Bus Revision 3.1 G2 Specification

SMBIOS System Management BIOS Reference Specification, Version 2.8

External BIOS simulator found at: http://h20464.www2.hp.com/index.html

Social and Environmental Responsibility

Eco-Label Certifications & This product has received or is in the process of being certified to the following approvals and may be **Declarations** labeled with one or more of these marks:

- ENERGY STAR® (energy-saving features available on selected configurations-Windows only)
- US Federal Energy Management Program (FEMP)
- China Energy Conservation Program
- The ECO declaration (TED)

The Z6 G4 is registered EPEAT® Gold in the US and Canada. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options

The battery in this product complies with EU Directive 2006/66/EC

Battery mass: 3q

Battery type: Lithium Metal

The battery in this product does not contain:

- Mercury greater than 5ppm by weight
- Cadmium greater than 10ppm by weight
- Lead greater than 40ppm by weight

Restricted Material Usage This product meets the material restrictions specified in HP's General Specification for the Environment.

HP Inc. is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis



Batteries

Low Halogen Statement This product is low-halogen except for power cords, external cables and peripherals. Service parts obtained after purchase may not be low-halogen.

and Recycling

End-of-Life Management HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. This product is greater than 90% recyclable by weight when properly disposed of at end of life.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment: Sustainability Report

Eco-label certifications:

http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html

ISO 14001 certificate:

http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html

Additional Information

- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. Product Disassembly Instructions
- Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and IS01043.

Packaging

HP Workstation product packaging meets the HP's General Specification for the Environment

- Does not contain restricted substances listed in HP Standard 011-1 General Specification for the Environment
- Does not contain ozone-depleting substances (ODS)
- Does not contain heavy metals (lead, mercury, cadmium or hexavalent chromium) in excess of 100 ppm sum total for all heavy metals listed
- Maximizes the use of post-consumer recycled content materials in packaging materials
- All packaging material is recyclable
- All packaging material is designed for ease of disassembly
- Reduced size and weight of packages to improve transportation fuel efficiency
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards formatting

Packaging Materials Internal **External**

Cushions and plastic bags made of low density polyethylene (LDPE).

Outer carton, accessories carton, and insert made of corrugated paper board.

Manageability

Industry Standard Specifications

This product meets the following industry standard specifications for manageability functionality:

DASH 1.1 (via Intel® LAN on motherboard)

Intel® Active Management Intel® Active Management Technology (AMT) 11.20 Technology (AMT)

An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 11.20 includes the following advanced management functions:

Power Management (on, off, reset, graceful shutdown, sleep and hibernate)



- Support in Max Power Savings (Shutdown and Hibernate Modes)
- Hardware Inventory (includes BIOS and firmware revisions)
- Hardware Alerting
- Agent Presence
- System Defense Filters
- Serial Over LAN (SOL)
- USB Redirect (Media Redirection)
- ME Wake-on-LAN (WOL), even with Maximum Power Savings Enabled
- DASH 1.1 compliance
- IPv6 Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance pre-schedule when the system connects to the IT or service provider console for maintenance.
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements
- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Local Time Sync to UTC
- Remote Memory Dump Command Creates memory dump for debug

Intel® vPro™ Technology The HP Z6 G4 Workstation supports Intel® vPro™ technology when configured as outlined below:

- Intel® Xeon® processor Scalable Family
- Intel® C622 chipset
- Intel® I219LM GbE LAN

Remote Manageability Software Solutions

The HP Z6 G4 Workstation is supported on the following remote manageability software consoles:

- LANDesk Management Suite (HP recommended solution)
- Microsoft System Center Configuration Manager

System Software Manager Service, Support, and Warranty For questions or support for manageability needs, please visit http://www.hp.com/go/easydeploy For questions or support for SSM, please visit: http://www.hp.com/go/ssm

On-site Warranty and Service (Note 1): Three-years, limited warranty and service offering delivers on-site, next business-day (Note 2) service for parts and labor and includes free telephone support (Note 3) 8am - 5pm. Global coverage (Note 2) ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. **NOTE 2:** On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Additional HP Care Pack Services



System Technical Specifications

Product Change Notification information by product is available at: http://www.hp.com/hps/carepack. Service levels and response times for HP Care Packs may vary depending on your geographic location.

- Program to proactively communicate Product Change Notifications (PCNs) and Customer Advisories by email to customers, based on a user-defined profile.
- PCNs provide advance notification of hardware and software changes to be implemented in the factory providing time to plan for transition.
- Customer Advisories provide concise, effective problem resolution, greatly reducing the need to call technical support.



Stable & Consistent Offerings

As part of its commitment to hardware, software, and solution innovation, HP is proud to introduce this breakthrough platform configuration stability to HP Workstation customers. HP Stable & Consistent Offerings are built on the foundation of a carefully chosen set of hardware and software designed and tested to work with all HP Z Workstation platforms through their end of life. These components and their corresponding HP Workstation platform compatibility are outlined in this section.

HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no special programs, no additional cost-no kidding. Simply select your hardware and software components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.

P	rn	ce	SS	n	rc

Product #	Offering
1XM44AA	Intel® Xeon® Gold 6128 processor
1XM49AA	Intel® Xeon® Silver 4114 processor
1XM51AA	Intel® Xeon® Silver 4108 processor

Ha		'IV	
па			

Prod	uct #
LQ03	37AA

Offering

1TB SATA 7200 RPM

Graphics

Product # 2TF08AA

Offering

AMD Radeon™ Pro WX 3100 4GB Graphics

M	ρ	m	n	rv	,
	c		v		

Product #	Offering
TBD	TBD

Optical and Removable Storage

Product #	Offering	
TBD	TBD	
TBD	TBD	



Technical Specifications - Processors

Intel® Xeon® Platinum 8180 processor

Intel® Xeon® Platinum 8160 processor

Intel® Xeon® Gold 6152 processor

Intel® Xeon® Gold 6154 processor

Intel® Xeon® Gold 6148 processor

Intel® Xeon® Gold 6146 processor

Intel® Xeon® Gold 6144 processor

Intel® Xeon® Gold 6142 processor

Intel® Xeon® Gold 6140 processor

Intel® Xeon® Gold 6138 processor

Intel® Xeon® Gold 6136 processor

Intel® Xeon® Gold 6134 processor

Intel® Xeon® Gold 6132 processor

Intel® Xeon® Gold 6130 processor

Intel® Xeon® Gold 6128 processor

Intel® Xeon® Gold 5120 processor

Intel® Xeon® Gold 5118 processor

Intel® Xeon® Gold 5115 processor

Intel® Xeon® Gold 5122 processor

Intel® Xeon® Silver 4116 processor

Intel® Xeon® Silver 4114 processor

Intel® Xeon® Silver 4112 processor

Intel® Xeon® Silver 4110 processor

Intel® Xeon® Silver 4108 processor

Intel® Xeon® Bronze 3106 processor

Intel® Xeon® Bronze 3104 processor



3.5 in; 8.9 cm

2.0ms

Technical Specifications - Hard Drives

STORAGE/HARD DRIVES

HP SAS (Serial Attached SCSI) Hard Drives for HP **Workstations**

HP 300GB SAS 15K SFF

HDD

Capacity 300GB Height 5.9 in: 15 cm Width

Media Diameter 12Gb/s SAS Interface

Synchronous Transfer Up to 1200 MB/s (SAS single port)

Rate (Maximum)

Buffer 128MB

Seek Time (typical reads, **Average**

includes controller overhead, including

settling)

Rotational Speed 15K rpm

Operating Temperature 41° to 131° F (5° to 55° C)

HP 1.2TB SAS 15K SFF HDD

1.2TB Capacity

Height 0.6 in; 1.53 cm

Width **Media Diameter** 2.5 in; 6.36 cm **Physical Size** 2.75 in; 6.99 cm

Interface SAS 6Gb/s Up to 600MB/s **Synchronous Transfer**

Rate (Maximum)

Buffer 64MB

Seek Time (typical reads, **Single Track** 0.18ms (max) includes controller Average 3.5ms overhead, including **Full Stroke** 7.17ms settling)



Technical Specifications - Hard Drives

SATA (Serial ATA) Hard
Drives for HP
Workstations

500GB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity 500GB
Height 1 in; 2.54 cm
Width Media Diamet

Media Diameter3.5 in; 8.9 cmPhysical Size4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s

Buffer 16MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average2 ms11 ms
Full Stroke21 ms

Rotational Speed 7,200 rpm **Logical Blocks** 976,773,168

Operating Temperature 41° to 131° F (5° to 55° C)

1TB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity 1TB

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600 MB/s

Buffer 64MB Cache Adaptive

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average2 msFull Stroke21 ms

Rotational Speed 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

2.0TB SATA 7200 rpm 6Gb/s 3.5" HDD
 Capacity
 2.0TB

 Height
 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0 Gb/s), NCQ Enabled

Synchronous Transfer Up to

Rate (Maximum)

Up to 600 MB/s

Buffer 64MB

Seek Time (typical reads, includes controller overhead, including cottling)Single Track overage1.0 msAverage overhead, including cottling cottling)Full Stroke over the service of the service over the

settling)

Rotational Speed 7,200 rpm Logical Blocks 3,907,029,168

Operating Temperature 41° to 131° F (5° to 55° C)

Technical Specifications - Hard Drives

3.0TB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity3.0TBHeight1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4.0 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Up to 6.0 Gb/s

Rate (Maximum)

Buffer 64MB

Seek Time (typical reads, includes controller overhead, including settling)Single Track overhead, one of the single track overhead, including settling0.6 msFull StrokeNot Specified

Rotational Speed 7,200 rpm

Operating Temperature 41° to 140° F (5° to 60° C)

1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) Capacity 1TB
Protocol SATA
Form Factor 3.5"
Controller AHCI
Reliability (MTBF) 2.0M hours
Rated Power On Hours 8760/yr
Annualized Failure Rate <0.62%

(based on Rated POH)

Rated for 24/7/365 YES

operation

Physical Size (Height)1 in; 2.54 cmPhysical Size (Width)4 in; 10.17 cmMedia Diameter3.5 in; 8.9 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Up to 600MB/s

Synchronous Transfer

Rate (Maximum)

Buffer 128MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average0.32ms
7.45msFull Stroke14.2ms

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s

Sequential Write up to 226MB/s

Enterprise Class Features High Reliability



Technical Specifications - Hard Drives

4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

Capacity 4TB

Height 0.275 in; 0.7 cm

Media Diameter Width 2.5 in; 6.36 cm **Physical Size** 2.75 in; 6.99 cm

Up to 600MB/s

Interface Serial ATA (6Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Buffer 128MB

Seek Time (typical reads, **Single Track** 0.7ms includes controller **Average** 8.5ms overhead, including **Full Stroke** 15.7ms

settling)

Rotational Speed 7,200 rpm

Operating Temperature 32° to 140° F (0° to 60° C)

500GB SATA 7.2K SED SFF HDD

Capacity 500GB

Height 0.275 in: 0.7 cm

Width **Media Diameter** 2.5 in; 6.36 cm **Physical Size** 2.75 in; 6.99 cm

Interface Serial ATA (6Gb/s) **Synchronous Transfer** Up to 600MB/s

Rate (Maximum)

32MB

Seek Time (typical reads, **Single Track** includes controller Average overhead, including **Full Stroke**

settling)

Buffer

Rotational Speed

Operating Temperature

32° to 140° F (0° to 60° C)

7,200 rpm

1ms

4.2ms

25ms (typical)



Technical Specifications - Hard Drives

SATA SSDs for	HP
Workstations	

HP 256GB SATA 6Gb/s SSD

Capacity 256GB **Protocol** SATA **Form Factor** 2.5" Controller **AHCI NAND Type** 3D TLC

Endurance 192TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in: 6.36 cm Interface SATA 6Gb/s **Synchronous Transfer** Up to 600MB/s

Rate (Maximum)

Operating Temperature

32° to 158° F (0° to 70° C)

Performance Sequential Read Sequential Write

500MB/s (max) 55K IOPS (max)

530MB/s (max)

Random Read Random Write

83K IOPS (max)

HP 256GB SATA 6Gb/s SED Opal 2 SSD

Capacity 256GB **Protocol** SATA **Form Factor** 2.5" Controller **AHCI NAND Type** 3D TLC

Endurance 192TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in: 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface 6Gb/s SATA

Synchronous Transfer Rate (Maximum)

Up to 550MB/s (Sequential Read)

Operating Temperature

32° to 158° F (0° to 70° C)

Performance

Sequential Read 530MB/s **Sequential Write** 500 MB/s **Random Read 55K IOPS Random Write 83K IOPS**

Self-Encrypting Drive

Support

OPAL 2

HP 512GB SATA 6Gb/s SSD

Capacity 512GB **Protocol** SATA Form Factor 2.5" Controller **AHCI NAND Type** 3D TLC

Endurance 388TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm

Technical Specifications - Hard Drives

Physical Size (Width) 2.5 in; 6.36 cm **Interface** SATA 6Gb/s

Synchronous Transfer

Rate (Maximum)

32° to 158° F (0° to 70° C)

Operating Temperature

Performance

Sequential Read 530 MB/s
Sequential Write 500 MB/s
Random Read 95K IOPS
Random Write 83K IOPS

Up to 550MB/s (Sequential Read)

HP 512GB SATA SED SSD

Capacity512GBProtocolSATAForm Factor2.5"ControllerAHCINAND Type3D TLC

Endurance 388TBW (TB Written)

Reliability (MTTF)1.5M hoursPhysical Size (Height)0.28 in; 0.7 cmPhysical Size (Width)2.5 in; 6.36 cmInterfaceSATA 6Gb/sSynchronous TransferUp to 600MB/s

Rate (Maximum)

Operating Temperature

32° to 158° F (0° to 70° C)

Performance Sequential Read 530 MB/s
Sequential Write 500 MB/s

1TB

Random Read 95K IOPS
Random Write 83K IOPS

Self-Encrypting Drive

Support

OPAL 1 and 2

HP 1TB SATA 6Gb/s SSD Capacity

Protocol SATA
Form Factor 2.5"
Controller AHCI
NAND Type 3D TLC

Endurance 400TBW (TB Written)

Reliability (MTTF)1.5M hoursPhysical Size (Height)0.28 in; 0.7 cmPhysical Size (Width)2.5 in; 6.36 cmInterfaceSATA 6Gb/s

Synchronous Transfer

Rate (Maximum)

Up to 550MB/s (Sequential Read)

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 530 MB/s
Sequential Write 500 MB/s

Random Read 95K IOPS Random Write 83K IOPS



Technical Specifications - Hard Drives

tions - Hard Drives				
HP 2TB SATA 6Gb/s SSD	Capacity	2TB		
	Protocol	SATA		
	Form Factor	2.5"		
	Controller	AHCI		
	NAND Type	3D TLC		
	Endurance 400TBW (TB Written)			
	Reliability (MTTF)	1.5M hours		
	Physical Size (Height)	0.28 in; 0.7 cm		
	Physical Size (Width)	2.5 in; 6.36 cm		
	Interface	SATA 6Gb/s		
	Synchronous Transfer Rate (Maximum)	Up to 550MB/s (Sequential Read)		
	Operating Temperature	32° to 158° F (0° to 70° C)		
	Performance	Sequential Read	530 MB/s	
		Sequential Write	500 MB/s	
		Random Read	95K IOPS	
		Random Write	83K IOPS	
HP Enterprise Class	Capacity	240GB		
240GB SATA SSD	Protocol	SATA		
	Form Factor	2.5"		
	Controller	AHCI		
	NAND Type	3D TLC		
	Endurance	2,200TBW (TB Written)		
	Reliability (MTTF)	2.0M hours		
	Physical Size (Height)	0.28 in; 0.7 cm		
	Physical Size (Width)	2.5 in; 6.36 cm		
	Interface	6Gb/s SATA		
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s		
	Operating Temperature	32° to 158° F (0° to 70° C)		
	Performance	Sequential Read	540 MB/s	
		Sequential Write	310 MB/s	
		Random Read	93K IOPS	
		Random Write	48K IOPS	
	Enterprise Class Features	High Endurance NAND Power Loss Protection End-to-End Data Protec	tion	
HP Enterprise Class	Capacity	480GB		
480GB SATA SSD	Protocol	SATA		
	Form Factor	2.5"		
	Controller	AHCI		
	NAND Type	3D TLC		
	Endurance	4,400TBW (TB Written)		
		-		



Physical Size (Height)

Reliability (MTTF)

2.0M hours

0.28 in; 0.7 cm

Technical Specifications - Hard Drives

Physical Size (Width) 2.5 in; 6.36 cm
Interface 6Gb/s SATA
Synchronous Transfer Up to 600MB/s
Rate (Maximum)

Operating Temperature

32° to 158° F (0° to 70° C)

Performance

Sequential Read 540 MB/s
Sequential Write 460 MB/s
Random Read 93K IOPS
Random Write 74K IOPS

Enterprise Class Features High Endurance NAND

Power Loss Protection
End-to-End Data Protection

PCIe SSDs for HP Workstations

HP Z Turbo Drive G2 256GB SSD Capacity 256GB
Protocol PCIe
Form Factor M.2
Controller NVMe
NAND Type MLC
Endurance 150TB
Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature

32° to 158° F (0° to 70° C)

Performance

Sequential Read 2800 MB/s
Sequential Write 1100 MB/s
Random Read 250K IOPS
Random Write 180K IOPS

HP Z Turbo Drive G2 512GB SSD Capacity512GBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D MLCEndurance300TBReliability (MTBF)1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature

32° to 158° F (0° to 70° C)

Performance

Sequential Read2800 MB/sSequential Write1600 MB/sRandom Read260K IOPSRandom Write260K IOPS

HP Z Turbo Drive G2 1TB Capacity

SSD

Capacity1TBProtocolPCIeForm FactorM.2ControllerNVMe

Technical Specifications - Hard Drives

NAND Type 3 D MLC
Endurance 600TB
Reliability (MTTF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3000 MB/s

Sequential Write1700 MB/sRandom Read360K IOPSRandom Write330K IOPS



Technical Specifications - Hard Drives

HP Z Turbo Drive Quad Pro 2x256GB PCIe SSD

Capacity 512GB **PCIe Protocol**

Form Factor PCIe Card, Full Height PCIe Slot

Controller **NAND Type** MLC 150TB **Endurance** Reliability (MTBF) 1.5M hours

Interface PCIe Gen3 x4 architecture **Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read 2800 MB/s

> **Sequential Write** 1100 MB/s **Random Read 250K IOPS Random Write 180K IOPS**

HP Z Turbo Drive Quad Pro 2x512GB PCIe SSD

1TB Capacity **Protocol** PCIe

Form Factor PCIe Card, Full Height PCIe Slot

Controller NVMe **NAND Type** 3D MLC **Endurance** 300TB Reliability (MTBF) 1.5M hours

Interface PCIe Gen3 x4 architecture **Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read 2800 MB/s

> **Sequential Write** 1600 MB/s Random Read **260 K IOPS Random Write 260K IOPS**

HP Z Turbo Drive Ouad Pro 2x1TB PCIe SSD

Capacity 2TB **Protocol** PCIe

Form Factor PCIe Card, Full Height PCIe Slot

Controller NVMe **NAND Type** 3D MLC **Endurance** 600TB

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance **Sequential Read** 3000 MB/s **Sequential Write** 1700 MB/s **Random Read 360 K IOPS**

Random Write 330K IOPS

HP Z Turbo Drive G2 256GB SED SSD

256GB Capacity **Protocol** PCIe

Technical Specifications - Hard Drives

Form Factor M.2 Controller NVMe **NAND Type** MLC

Endurance 150TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance **Sequential Read** 2800 MB/s

> **Sequential Write** 1100 MB/s **Random Read 250K IOPS Random Write 180K IOPS**

Self-Encrypting Drive OPAL 2

Support

HP Z Turbo Drive G2 512GB SED SSD

Capacity 512GB **PCIe Protocol Form Factor** M.2 Controller NVMe **NAND Type** MLC

300TBW (TB Written) **Endurance**

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

32° to 158° F (0° to 70° C) **Operating Temperature**

Performance

Sequential Read 2800 MB/s **Sequential Write** 1600 MB/s **Random Read 260K IOPS Random Write 260K IOPS**

Self-Encrypting Drive OPAL 2

Support

HP Z Turbo Drive Quad Pro Capacity 2x1TB PCIe SSD

2TB **Protocol** PCIe

Form Factor PCIe Card, Full Height PCIe Slot

Controller NVMe **NAND Type** 3D MLC **Endurance** 600TB

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3000 MB/s Sequential Write 1700 MB/s **Random Read 360K IOPS**

Random Write 330K IOPS

HP Z Turbo Drive G2 256GB TLC SSD

Capacity 256GB **Protocol PCIe Form Factor** M.2



Technical Specifications - Hard Drives

Controller NVMe NAND Type 3D TLC

Endurance 75TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 2800 MB/s

Sequential Write 320 MB/s (1100 MB/s

max/Turbo)

Random Read 250K IOPS **Random Write** 180K IOPS

HP Z Turbo Drive G2 512GB TLC SSD Capacity512GBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 150TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 2800 MB/s

Sequential Write 660 MB/s (1600 MB/s

max/Turbo)

Random Read 260K IOPS **Random Write** 260K IOPS

HP Z Turbo Drive G2 1TB TLC SSD

 Capacity
 1TB

 Protocol
 PCle

 Form Factor
 M.2

 Controller
 NVMe

 NAND Type
 3D TLC

Endurance 300TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3000 MB/s

Sequential Write 1150 MB/s (1700 MB/s

max/Turbo)

Random Read 360K IOPS **Random Write** 330K IOPS

256GB (one M.2 PCIe NVMe module)

HP Z Turbo Drive Quad Pro Capacity 256GB SSD module

•

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Technical Specifications - Hard Drives

HP Z Turbo Drive Quad Pro Capacity 512GB (one M.2 PCIe NVMe module)

512GB SSD module

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

HP Z Turbo Drive Quad Pro Capacity 1TB (one M.2 PCIe NVMe module)

1TB SSD module

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)



Technical Specifications - Hard Drive Controllers

HARD DRIVE CONTROLLERS

Microsemi SmartHBA2100-4i4e SAS RAID Levels

Controller

PCI Bus 8 lanes, PCI Express 3.0

Offers Integrated RAID (0, 1, and 10) **PCI Data Burst Transfer** Half Duplex x8, PCIe, 8000 MB/s

Rate

SAS Bandwidth Half Duplex 1200 MB/s per lane

PCI Card Type 3.3V Add-in Card 12 V ± 10% **PCI Voltage**

PCI Power 9.8W typical, Airflow min 200 LFM

Bracket Full height and low profile **Certification Level** PCI Express 3.0 compliant

SAS Processor Microsemi SmartIOC 2100 SAS IO Controller **Internal Connectors** One x4 internal mini-SASHD (SFF-8643) One x4 external mini-SASHD (SFF-8644) **External Connectors**

Maximum Number of SCSI 256 Non-RAID SAS/SATA devices

Devices

LED Indicators Connector for Drive Activity Light



Technical Specifications - Graphics

GRAPHICS

NVIDIA® Quadro® P400 1st GFX 2GB Graphics

Form Factor Dimensions: 2.713" H x 5.7" L

Single Slot, Low Profile

Cooling: Active Weight: 129 grams

Graphics Controller NVIDIA® Quadro® P400 Graphics Card

GP107-825 GPU

256 NVIDIA® CUDA® cores Max Power: 30 Watts

Bus Type PCI Express 3.0 x16

Memory Size: 2 GB GDDR5, 2000 MHz

Memory Interface: 64-bit Memory Bandwidth: 32 GB/s

3mDP Outputs Connectors

Maximum Resolution DisplayPort™ 1.4:

> - up to 3x 5120 x 2880 x 24 bpp @ 60Hz supports Multi-Stream Transport (MST)

10-bit internal display processing pipeline **Image Quality Features**

10-bit scan-out support

Display Output 3 mDP Connectors

Shading Architecture

Full Microsoft DirectX® 12 Shader Model 5.1

Supported Graphics APIs OpenGL® 4.5 DirectX® 12

Vulkan™ 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL™

Available Graphics

Drivers

Microsoft Windows 10 Microsoft Windows 8.1 Microsoft Windows 7

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

NVIDIA® Quadro® P600 1st Form Factor

GFX 2GB Graphics

Dimensions: 2.713" H x 5.7" L Single Slot, Low Profile

Cooling: Active Weight: 129 grams

Graphics Controller NVIDIA® Quadro® P600 Graphics Card

GP107-850 GPU

384 NVIDIA® CUDA® cores Max Power: 40 Watts

Bus Type PCI Express 3.0 x16

Technical Specifications - Graphics

Memory Size: 2 GB GDDR5, 2000 MHz

Memory Interface: 128-bit Memory Bandwidth: 64 GB/s

Connectors 4mDP Outputs **Maximum Resolution** DisplayPort™ 1.4:

up to 4x 5120 x 2880 x 24 bpp @ 60Hz
 supports Multi-Stream Transport (MST)

Image Quality Features 10-bit internal display processing pipeline

10-bit scan-out support

Display Output 4 mDP Connectors

Shading Architecture Full Microsoft DirectX® 12 Shader Model 5.1

Supported Graphics APIs OpenGL® 4.5

DirectX® 12 Vulkan™ 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL™

Available Graphics

Drivers

Microsoft Windows 10 Microsoft Windows 8.1 Microsoft Windows 7

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

AMD FirePro™ W2100 2GB Graphics **Form Factor** Low Profile, half length (full-height bracket included)

Graphics Controller AMD FirePro™ W2100 professional graphics based on Oland GPU.

GPU: 320 Stream Processors organized into 5 Compute Units

GPU Frequency: 630Mhz

Power: 26W Cooling: Active

Bus Type PCI Express® x8, Generation 3.0

Memory 2GB DDR3 memory

Memory Bandwidth: up to 28.8 GB/s

Memory Width: 128 bit

Connectors 2x Display Port[™] 1.2 connectors

Factory Configured: No video cable adapter included After market option kit: No video cable adapter included

Additional DisplayPort™-to-VGA or DisplayPort™-to-DVI adapters are

available as Factory Configuration or Option Kit accessories.

Maximum Resolution DisplayPort™ 1.2:

- up to 4096x2160 x 24 bpp @ 60Hz



Technical Specifications - Graphics

Dual Link DVI(I) (requires adapter cable): - up to 2560 x 1600 x 32 bpp @ 60Hz

Single Link-DVI(I)(requires adapter cable): - up to 1920 x 1200 x 32 bpp @ 60Hz

VGA (requires adapter cable):

- up to 1920 x 1200 x 32 bpp @ 60Hz

Image Quality Features Advanced support for 8-bit, 10-bit, and 16-bit per RGB color component.

High bandwidth scaler for high quality up and downscaling.

Display Output 2 x DisplayPort™ 1.2a

Maximum number of displays: 2

Shading Architecture Shader Model 5.0

Supported Graphics APIs OpenCL™ 1.2, DirectX® 11.2/12, OpenGL® 4.4

OpenGL® 4.4 support with driver release 14.301.xxx

OpenCL™ 1.2 conformance expected with drive release 14.301.xxx

Available Graphics

Drivers

Windows 10 (64-bit)
Windows 8.1 (64-bit)

Windows 7 (64-bit)

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site

http://welcome.hp.com/country/us/en/support.html

Notes Depending on the card model, native DisplayPort™ connectors and/or

certified DisplayPort[™] active or passive adapters to convert your monitor's native input to your card's DisplayPort[™] or Mini-DisplayPort[™] connector(s)

may be required. See www.amd.com/FirePro™ for details.

NVIDIA® Quadro® P1000 1st GFX 4GB Graphics **Form Factor** Dimensions:2.713" H x 5.7" L

Single Slot, Low Profile

Cooling: Active Weight: 129 grams

Graphics Controller NVIDIA® Quadro® P1000 Graphics Card

GP107-860 GPU

640 NVIDIA® CUDA® cores Max Power: 47 Watts

Bus Type PCI Express 3.0 x16

Memory Size: 4 GB GDDR5, 2500 MHz

Memory Interface: 128-bit memory interface Memory Bandwidth: 80 GB/s memory bandwidth

Connectors 4mDP Outputs **Maximum Resolution** DisplayPort™ 1.4:

Technical Specifications - Graphics

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz

- supports Multi-Stream Transport (MST)

Image Quality Features 10-bit internal display processing pipeline

10-bit scan-out support

Display Output 4 mDP Connectors

Shading Architecture

Full Microsoft DirectX® 12 Shader Model 5.1

Supported Graphics APIs OpenGL® 4.5

DirectX® 12 Vulkan™ 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL™

Available Graphics

Drivers

Microsoft Windows 10 Microsoft Windows 8.1 Microsoft Windows 7

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

NVIDIA® Ouadro® P2000 1st GFX 5GB Graphics

Form Factor

Dimensions: 4.4"Hx7.9"L

Single Slot Cooling: Active Weight: 260 grams

Graphics Controller NVIDIA® Quadro® P2000 Graphics Card

Power: 75 Watts

Bus Type PCI Express 3.0 x16 Memory Size: 5GB GDDR5

> Memory Bandwidth: 140 GB/s Memory Width: 160-bit

4x DisplayPort™ 1.4 Connectors

> Factory Configured Option: No adapter included with card After Market Option: No video cable adapter included

Additional DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories.

Maximum Resolution

DisplayPort™: - up to 5120 x 2880 x 24 bpp @ 60Hz

- supports High Bit Rate 2 (HBR2) and Multi-Stream Transport (MST) DP 1.3

& 1.4 ready.

DL-DVI(I) output:

- up to 2560 x 1600 x 32 bpp @ 60 Hz

Single Link-DVI(I) output:

- up to 1920 x 1200 x 32 bpp @ 60Hz

HDMI 2.0 (requires DP to HDMI adapter):

5120 x 2880 x 24 bpp @ 60Hz

Technical Specifications - Graphics

Image Quality Features 12-bit internal display pipeline (hardware support for 12-bit scanout on

supported panels, applications and connection)

Stereoscopic 3D display support including NVIDIA® 3D Vision™ technology,

NVIDIA® Mosaic and nView.

Display Output Maximum number of displays

- 4 direct attached monitors

Maximum number of monitors across all available Quadro P2000 outputs

is 4.

Shading Architecture

Supported Graphics APIs

OpenGL® 4.5

Shader Model 5.1

DirectX® 12

API support includes:

CUDA C, CUDA C++, DirectCompute 5.0, OpenCL™, Java, Python, and Fortran

software

Available Graphics

Drivers

Microsoft Windows 10

Microsoft Windows 7 Professional 64bit

Linux® - Full OpenGL® implementation, complete with NVIDIA® and ARB

extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

Radeon™ Pro WX 3100 4GB Graphics **Form Factor**

Low-Profile Single Slot (6.6" Length)

Graphics Controller

Polaris12 GL

GPU: 512 Stream Processors organized into 8 Compute Units

Power: 50 Watts Cooling: Active

Memory

4GB GDDR5 memory

Memory Bandwidth: 6 Gbps / 96 GB/s

Memory Width: 128 bit

Connectors

2x Mini DisplayPort™ 1.4 plus 1x DisplayPort™ 1.4 – HDR ready connectors

with HBR3 and MST support.

Factory Configured: No adapters included

After market option kit: One mDP-to-DP cable adapters included

Additional Mini DisplayPort™-to-DisplayPort™, DisplayPort™-to-VGA or DisplayPort™-to-DVI adapters are available as Factory Configuration or

Option Kit accessories.

Maximum Resolution

5K support @ 60Hz

• 1x single-cable 5K monitor, or 2x dual-cable 5K monitors

3x 4K support @ 60Hz

Image Quality Features

Advanced support for 8-bit and 10-bit per RGB color component. High

bandwidth scaler for high quality up and downscaling



Technical Specifications - Graphics

Display Output 3 full physical DP1.3 HBR3 / DP1.4 HDR outputs

FreeSync support

GPU Architecture **Polaris**

Supported Graphics APIs DirectX°12

OpenGL® 4.5 OpenCL™ 2.0 Vulkan™ 1.0

Available Graphics

Drivers

Windows 10 64-bit

(Windows® 7 64-bit available from AMD)

Linux[®] 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

1. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.

2. AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FirePro™ and Radeon™ Pro products, which are designed to intelligently manage GPU power consumption

in response to certain GPU load conditions.

3. As of September 2016, certified for DisplayPort™ 1.4 HBR3 and ready for DisplayPort™ 1.4 HDR based on independent verification by DisplayPort™ testing authority. HDR content requires that the system be configured with a fully HDRready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed

mode content requires operating system support.

Radeon™ Pro WX 4100 **4GB Graphics**

Form Factor

Low-Profile Single Slot (6.6" Length)

Graphics Controller

Polaris 11 Baffin GL XT

GPU: 1024 Stream Processors organized into 16 Compute Units

Power: 50 Watts Cooling: Active

Memory 4GB GDDR5 memory

Memory Bandwidth: 6 Gbps / 96 GB/s

Memory Width: 128 bit

Connectors 4x Mini DisplayPort™ 1.4 – HDR ready connectors with HBR3 and MST

support.

Factory Configured: Four mDP-to-DP cable adapters included After market option kit: Four mDP-to-DP cable adapters included

Additional DisplayPort™-to-VGA or DisplayPort™-to-DVI adapters are

available as Factory Configuration or Option Kit accessories.

Technical Specifications - Graphics

Maximum Resolution 5K support @ 60Hz

1x single-cable 5K monitor, or 2x dual-cable 5K monitors

4x 4K support @ 60Hz

Image Quality Features Advanced support for 8-bit and 10-bit per RGB color component. High

bandwidth scaler for high quality up and downscaling

Display Output 4 full physical DP1.3 HBR3 / DP1.4 HDR outputs

FreeSync support

GPU Architecture **GCN 4th Generation**

Supported Graphics APIs DirectX°12

OpenGL® 4.5 OpenCL™ 2.0 Vulkan™ 1.0

Available Graphics

Drivers

Windows 10 64-bit Windows® 7 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

4. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card. monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.

5. AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FirePro[™] and Radeon[™] Pro products, which are designed to intelligently manage GPU power consumption in response to certain GPU load conditions.

6. As of September 2016, certified for DisplayPort™ 1.4 HBR3 and ready for DisplayPort™ 1.4 HDR based on independent verification by DisplayPort™ testing authority. HDR content requires that the system be configured with a fully HDRready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windows mode content requires operating system support.

NVIDIA® Ouadro® P4000 1st GFX 8GB Graphics

Dimensions: 4.4"H x 9.5"L Form Factor

Single-slot, full-height

Weight: 475 grams (without extender)

Graphics Controller NVIDIA® Quadro® P4000 Graphics Card

GPU: GP104 with 1792 CUDA cores

Power: 120 Watts

Bus Type PCI Express 3.0 x16 Memory

Size: 8GB GDDR5

Memory Bandwidth: 243 GB/s Memory Width: 256-bit



Technical Specifications - Graphics

Connectors 4 x DisplayPort 1.4

3-pin mini-DIN connector via optional bracket

1 x 6-pin auxiliary power connector 4-pin header for stereo signal SYNC connector for Quadro® Sync II

2 x SLI connectors

Factory Configured Option: No video cable adapter included After Market Option: No video cable adapter included

Additional DisplayPort-to-VGA, DisplayPort-to-HDMI, or DisplayPort-to-

DVI adapters are available as accessories

Maximum Resolution Dual-link internal TMDS (DVI 1.0):

- up to 2560 x 1600 x 32 bpp @ 60 Hz

Single-link internal TMDS (DVI 1.0): - up to 1920 x 1200 x 32 bpp @ 60 Hz

HDMI[™] 2.0b (requires DP to HDMI adapter): - up to 5120 x 2880 x 24 bpp @ 60Hz

DisplayPort:

up to 4096 x 2160 x 30 bpp @ 60Hz
 up to 2560 x 1600 x 30 bpp @ 120 Hz

- supports High Bit Rate 2 (HBR2) and Multi-Stream Transport (MST)

Using two DP outputs, the P4000 can drive one dual DP input display with

5120 x 2880 x 30 bpp @ 60Hz resolution.

Image Quality Features Advanced support for 8-bit, 10-bit, and 12-bit per RGB color

component.

HDCP 2.2 support over DisplayPort, DVI, and HDMI connectors

NVIDIA 3D Vision™ and other 3D stereo technologies

NVIDIA Mosaic and nView

Display Output Maximum number of displays

- 4 direct attached monitors

Maximum number of monitors across all available Quadro P4000 outputs

is 4.

Shading Architecture Shader Model 5.1

Supported Graphics APIs OpenGL 4.5

DirectX 12 Vulcan 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute 5.0, OpenCL, Java, Python, and Fortran

Available Graphics

Drivers .

Microsoft Windows 10 Microsoft Windows 7

Linux - Full OpenGL implementation, complete with NVIDIA and ARB

extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:



Technical Specifications - Graphics

Notes

http://welcome.hp.com/country/us/en/support.html

- Quadro P4000 offered as Factory Configured Option does not include a video cable adapter. Video cable adapters must be ordered separately.
- 2. Quadro P4000 offered as an After Market Option does not include video cables. Video cable adapters must be ordered separately.

NVIDIA® Quadro® P5000 1st GFX 16GB **Graphics**

Form Factor

Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 815 grams / 1.80 lbs

Graphics Controller

Quadro™ P5000 graphics

GPU: 2560 NVIDIA® CUDA® Parallel Processing Cores

Power: 180 Watts Cooling: Active

Memory

16GB GDDR5X memory

Memory Bandwidth: Up to 288 GB/s

Memory Width: 256 bit

ECC Memory (disabled by default)

Connectors

DP (x4) with HDR support

DL-DVI(D)

3-pin mini-DIN connector

SLI connector

Quadro Sync connector (compatible with Quadro II Sync)

One 8-pin auxiliary power connector

Factory configured option: No video cable adapter included with card. After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories.

Maximum Resolution 5K support @ 60Hz

1x single-cable 5K monitor, or 2x dual-cable 5K monitors

Image Quality Features

Advanced support for 8-bit, 10-bit, and 12-bit per RGB

color component.

HDCP 2.2 support over DisplayPort™, DVI, and HDMI

connectors

NVIDIA 3D Vision™ and other 3D stereo technologies NVIDIA® Mosaic and nView Desktop Management

Display Outputs1

4x DP1.4 HDR outputs (up to 3840x2160 UHD @ 120Hz refresh, or up

to 8K at 30Hz)

Technical Specifications - Graphics

1x Dual-link DVI-D output (up to 2560 x 1600 @ 60 Hz and

1920x1200 @ 120 Hz)

GPU Architecture NVIDIA® Pascal™

Supported Graphics

APIs

DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

Available Graphics

Drivers

Windows® 10 64-bit Windows® 7 64-bit

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

Notes 1- Supports up to a total of 4 displays

NVIDIA® Quadro® P6000 1st GFX 24GB Graphics **Form Factor** Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 967 grams / 2.14 lbs

Graphics Controller NVIDIA® Quadro® P6000 graphics

GPU: 3840 NVIDIA® CUDA® Parallel Processing Cores

Power: 250 Watts Cooling: Active

Memory 24GB GDDR5X memory

Memory Bandwidth: Up to 432 GB/s

Memory Width: 384 bit

ECC Memory (disabled by default)

Connectors DP (x4) with HDR support

DL-DVI(I)

3-pin mini-DIN connector

SLI connector

Quadro Sync connector (compatible with Quadro II Sync)

One 8-pin auxiliary power connector

Factory configured option: No video cable adapter included with

card.

After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort[™] to VGA, DisplayPort[™] to DVI, and DisplayPort[™] to Dual-Link DVI adapters available as accessories.



Technical Specifications - Graphics

Maximum Resolution 5K support @ 60Hz

1x single-cable 5K monitor, or 2x dual-cable 5K monitors

Image Quality Features Advanced support for 8-bit, 10-bit, and 12-bit per RGB

color component.

HDCP 2.2 support over DisplayPort™, DVI, and HDMI

connectors

NVIDIA® 3D Vision™ and other 3D stereo technologies

NVIDIA® Mosaic and nView

Display Outputs¹ 4x DP1.4 HDR outputs (up to 3840x2160 UHD @ 120Hz refresh, or

up to 8K at 30Hz)

1x Dual-link DVI-D output (up to 2560 x 1600 @ 60 Hz and

1920x1200 @ 120 Hz)

GPU Architecture NVIDIA® Pascal™

Supported Graphics

APIs

DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

Available Graphics

Drivers

Windows® 10 64-bit Windows® 7 64-bit

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

Notes 1- Supports up to a total of 4 displays

Radeon™ Pro WX 7100 8GB Graphics

Form Factor

Full-Height Single Slot (9.5" Length)

Graphics Controller Radeon™ Pro WX 7100 graphics

GPU: 2304 Stream Processors organized into 36 Compute Units

Power: 130 Watts Cooling: Active

Memory 8GB GDDR5 memory

Memory Bandwidth: 7 Gbps / 224 GB/s

Memory Width: 256 bit

Connectors 4x DisplayPort™ 1.4 – HDR ready connectors with HBR3 and MST support.

Factory Configured: No video cable adapter included After market option kit: No video cable adapter included

Additional DisplayPort™-to-VGA or DisplayPort™-to-DVI adapters are

available as Factory Configuration or Option Kit accessories.

Technical Specifications - Graphics

Maximum Resolution 5K support @ 60Hz

1x single-cable 5K monitor, or 2x dual-cable 5K monitors

Image Quality Features Advanced support for 8-bit, 10-bit, and 16-bit per RGB color

component. High bandwidth scaler for high quality up and

downscaling

Display Output 4 full physical DP1.3 HBR3 / DP1.4 HDR outputs

FreeSync support

GPU Architecture GCN 4th Generation

Supported Graphics APIs DirectX°12

OpenGL[®] 4.5 OpenCL™ 2.0 Vulkan™ 1.0

Available Graphics

Drivers

Windows 10 64-bit Windows® 7 64-bit Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

- HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.
- 8. Radeon VR Ready Creator Products are select Radeon Pro and AMD FirePro™ GPUs that meet or exceed the Oculus Rift or HTC Vive recommended specifications for video cards/GPUs. Other hardware (including CPU) and system requirements recommended by Oculus Rift or HTC Vive should also be met in order to operate the applicable HMDs as intended. As VR technology, HMDs and other VR hardware and software evolve and/or become available, these criteria may change without notice.
- AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FirePro[™] and Radeon[™] Pro products, which are designed to intelligently manage GPU power consumption in response to certain GPU load conditions.
- 10. As of September 2016, certified for DisplayPort™ 1.4 HBR3 and ready for DisplayPort™ 1.4 HDR based on independent verification by DisplayPort™ testing authority. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.



Technical Specifications – Optical and Removable Storage

OPTICAL AND REMOVABLE STORAGE

HP 9.5mm Slim DVD Writer

Description 9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types DVD+R

DVD+RW DVD+R DL DVD-R DL DVD-R **DVD-RW** CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

> Full Stroke DVD < 200 ms (seek) Full Stroke CD < 200 ms (seek)

Maximum Data Transfer

Rates

CD ROM Read CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

> DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Power Source SATA DC power receptacle

> 5 VDC ± 5%-100 mV ripple p-p **DC Power Requirements**

DC Current 5 VDC -< 800 mA typical, <1600 mA

maximum

84° F (29° C)

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions noncondensing)

Relative Humidity Maximum Wet Bulb Temperature 10% to 80%

Operating Systems Supported

Windows 10. Windows 7 Professional 64-bit. Windows Vista Business 64*, Windows 2000.

Red Hat® Enterprise Linux® (RHEL) WS4**, 5, 6 Desktop/Workstation

SUSE Linux® Enterprise Desktop 10 & 11

* No driver is required for this device. Native support is provided by the

operating system.

Kit Contents HP SATA DVD Writer drive, installation guide.

HP 9.5mm Slim DVD-ROM Description Drive

Mounting Orientation

9.5mm height, tray-load Either horizontal or vertical



Technical Specifications – Optical and Removable Storage

Interface Type SATA / ATAPI Dimensions (WxHxD) 128 x 9.5 x 127mm

Disc Capacity DVD-ROM Single layer: Up to 4.7 GB

Double layer: Up to 8.5 GB

Access Times DVD-ROM Single Layer < 110 ms (typical)

> CD-ROM Mode 1 < 110 ms (typical) Full Stroke DVD < 230 ms (typical) < 220 ms (typical) Full Stroke CD

Power SATA DC power receptacle Source

> 5 VDC ± 5%-100 mV ripple p-p **DC Power Requirements**

DC Current 5 VDC - <800mA typical, < 1600 mA

maximum

10% to 80%

Operating Environmental Temperature

(all conditions noncondensing)

Operating Systems

Supported

Relative Humidity

41° to 122° F (5° to 50° C)

Maximum Wet Bulb Temperature 84° F (29° C) Windows 8.1, Windows 7 Professional 64-bit.

Windows Vista Business 64*, Windows 2000. Red Hat® Enterprise Linux® (RHEL) WS4**, 5, 6 Desktop/Workstation

SUSE Linux® Enterprise Desktop 10 & 11

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents 9.5mm Slim DVD-ROM Drive, 5.25" ODD Bay adapter/carrier, slim SATA

data/power cable, installation guide

HP 9.5mm Slim BDXL Blu- Description

Ray Writer

Mounting Orientation

9.5mm height, tray-load Either horizontal or vertical

Interface Type

SATA/ATAPI

Dimensions (WxHxD) Supported Media Types 128 x 9.5 x 127mm BD-ROM

BD-R BD-RE DVD+R

DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

Blu-ray 25 GB (single-layer) 50 GB (dual-layer)

100/128 GB (BDXL)

Full Stroke DVD < 230 ms (seek)

Technical Specifications – Optical and Removable Storage

Full Stroke CD < 220 ms (seek)

< 230 ms (seek) (Full Stroke Blu-ray) Blu-ray

Startup Time (Time to drive ready from tray

loading)

BD-ROM (SL/DL) 25S / 28S BD-R (SL/DL) 255 / 285 BD-RE (SL/DL) 255 / 285 DVD-ROM (SL/DL) 18S / 18S DVD-R (SL/DL) **25S / 25S**

DVD-RW **25S**

DVD+R (SL/DL) 255 / 255

DVD+RW 255 CD-ROM **15S**

Maximum Data Transfer CD ROM Read

Rates

CD-ROM, CD-R Up to 24X CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X BD-ROM Up to 6X

Blu-ray

BD-ROM DL Up to 6X BD-R Up to 6X BD-R DL Up to 6X BD-R Up to 6X BD-RE SL/DL Up to 6X

SATA DC power receptacle Power Source

> **DC Power Requirements** $5 \text{ VDC} \pm 5\%-100 \text{ mV ripple p-p}$ 5 VDC -900 mA typical, 2000mA DC Current

> > maximum

Operating Environmental Temperature (all conditions non-

Operating Systems

condensing)

Supported

Relative Humidity

41° to 122° F (5° to 50° C) 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C) Windows 8.1, Windows 7 Professional 64-bit, Windows Vista Business 64*, Windows 2000.

Red Hat® Enterprise Linux® (RHEL) WS4**, 5, 6 Desktop/Workstation

SUSE Linux® Enterprise Desktop 10 & 11

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents 9.5mm Slim BDXL Blu-Ray Writer, 5.25" ODD Bay adapter/carrier, slim

SATA data/power cable, installation guide

As Blu-ray is a new format containing new technologies, certain disc. digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may

Technical Specifications – Optical and Removable Storage

require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

HP DX115 Removable Drive Enclosure Interface Type Compatible with SAS or SATA controllers. Offers 6Gb/s performance when

used with 6Gb/s HDDs.

Dimensions (WxHxD) 147.6mm W x 41.1mm H x 205mm D

(5.81" W x 1.62" H x 8.08" D)

Approvals Frame and Carrier: 1.73 kg (3.8 lbs.)

Carrier: 0.45 kg (1 lbs.)

HP SD Card Reader

Description Supports hardware ECC (Error Correction Code) function

Supports hardware CRC (Cyclic Redundancy Check) function

Supports SD 4-bit parallel transfer mode

Interface Type

USB 3.0 High-speed interface

Dimensions (WxHxD) 1.15 x .9 x .15 in (29.00 x 23.6 x 3.15 mm) Fits conveniently in the Front IO

Bay

Supported Media Types Secure Digital Card (SD)

Secure Digital High Capacity (SDHC)
SD Extended Capacity Memory Card (SDXC)

SD Ultra High Speed II(SD UHSII)

These additional media types are supported with a card adapter.

Memory Stick Micro (M2)

miniSD

miniSD High Capacity

Micro SD Memory Card (MicroSD)

Micro SD High Capacity Memory Card (MicroSDHC)

Test Parameters/Conditions - Power applied, unit operating on system

±5%

Operating Systems Supported Windows 10

No driver is required for this device. Native support is provided by the

operating system.

Media card reader

Kit Contents

Approvals USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport

Specification Rev. 1.0.

Compliant Intel® Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE,

BSMI, C-Tick, VCCI, MIC, cUL, TUVT

Weight 0.35 lbs. (0.16 kg)

Technical Specifications - Controller Cards

CONTROLLER CARDS

HP Thunderbolt-3 Dual Port2 PCIe 1-port I/O Card Data Transfer Rate
Devices Supported

Supports up to 40 Gb/s (40,000 Mb/s)

Thunderbolt™, Thunderbolt™ 2 and Thunderbolt™ 3 certified for Windows

devices

Bus Type PCIe card, full height PCIe slots

Ports Two Thunderbolt™ 3 external USB type-C output connectors (Rear)

Two full size DisplayPort input connectors (Rear)

Internal Connectors One 2x5-Pin header connector

System Requirements Genuine Windows 10 Professional 64-bit, available dedicated PCH PCIe

slot.

Temperature - Operating 50° to 131° F (10° to 55° C) **Temperature - Storage** -22° to 140° F (-30° to 60° C)

Relative Humidity -

Operating

20% to 80%

Compliances FCC Part 15B, cULus 60950, CE Mark EN55022B(1995)/EN55024-1998 STD,

Taiwan BSMI CNS13438, Korea MIC

Operating Systems

Supported

Genuine Windows 10 Professional 64-bit.

Kit Contents HP Thunderbolt™ 3 Dual Port PCIe I/O Card, 2- DisplayPort cables, GPIO

(General-Purpose Input/Output) cables, Installation documentation and

warranty card.



^{*}Maximum speed requires DisplayPort™ and PCIe aggregation.

Technical Specifications - Networking and Communications

NETWORKING AND COMMUNICATIONS

Integrated Intel® I219LM Connector **RJ-45**

> Intel® I219LM Controller **Data Rates Supported** 10/100/1000 Mbps

Boot ROM Support PXE, UEFI

Connect Speed LED

Indicators

Link/Activity LED

Off = No link

Blinking = Activity

Speed LED

Off = 10Mbps

Amber = 100Mbps

Green = 1000Mbps

Management Capabilities Intel® Active Management Technology™ 11

Integrated Intel® X722 for 1GbE

Connector 1 RJ-45

Controller Intel® X722 for 1GbE

Data Rates Supported 1000 Mbps **Boot ROM Support** PXE, UEFI

Connect Speed LED Indicators

Off = No link Blinking = Activity

Speed LED

Link/Activity LED

Off = No Link

Green = 1000Mbps

Management Capabilities Wake-On-LAN

HP Z Dual 10GbE Network Networking Interface

Module

2 RJ-45

System Interface Networking Speeds

Supported

Cabled from Dedicated Rear I/O Slot 1Gbps, 10Gbps

Cabling (up to 100m) Cat5e (or higher) for 1Gbps

Cat6a (or higher) for 10Gbps

Power Consumption 5.5W at 1Gbps (active-typical) **Physical Dimensions**

Connect Speed LED

Indicators

11.2W at 10Gbps

0.875 in x 3 in x 2.75 in

Link/Activity LED

Off = No link Blinking = Activity

Speed LED

Amber = 1Gbps

Green = 10Gbps

0 °C to 55 °C (32 °F to 131 °F) **Operating Temperature**

Intel® I210-T1 **Networking Interface** 1 RJ-45

Technical Specifications - Networking and Communications

System Interface

Networking Speeds

Supported

PCI Express 2.1 x1

10Mbps, 100Mbps, 1Gbps

Cabling (up to 100m) Cat3 (or higher) for 10Mbps

> Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps

Power Consumption (active-typical)

0.81W

Physical Dimensions Length: 6.7cm (2.64 inches)

(Bracket) Width: 1.8cm (0.709 inches)

Full-height end bracket: 12.07cm (4.755 inches) Low-profile end bracket: 8cm (3.15 inches)

Connect Speed LED Indicators

Link/Activity LED Off = No link

Blinking = Activity

Speed LED

Off = 10Mbps

Green = 100Mbps

Amber = 1Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Hardware Certifications

USA: FCC B, EU: UL CE, Japan: VCCI. Taiwan: BSMI.

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Intel® 1350-T2

Networking Interface 2 RJ-45

System Interface PCI Express 2.1 x4

Networking Speeds

Supported

10Mbps, 100Mbps, 1Gbps

Cabling (up to 100m) Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps

Power Consumption (active-typical)

4.4W

Physical Dimensions Length: 13.54cm (5.33 inches) Width: 6.89 (2.71 inches)

> Full-height end bracket: 12.0cm (4.725 inches) Low-profile end bracket: 7.92cm (3.117 inches)

Connect Speed LED Indicators

Link/Activity LED

Off = No link Blinking = Activity

Speed LED

Off = 10Mbps

Green = 100Mbps

Amber = 1Gbps

Operating Temperature 0 °C to 55 °C (32 °F to 131 °F)

Technical Specifications - Networking and Communications

Hardware Certifications USA: FCC B.

> EU: UL CE. Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Intel® 1350-T4 **Networking Interface** 4 RJ-45

> System Interface PCI Express 2.1 x4

Networking Speeds

Supported

10Mbps, 100Mbps, 1Gbps

Cabling (up to 100m) Cat3 (or higher) for 10Mbps

> Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps

Power Consumption (active-typical)

Physical Dimensions

Length: 13.54cm (5.33 inches)

Width: 6.89 (2.71 inches)

Full-height end bracket: 12.0cm (4.725 inches) Low-profile end bracket: 7.92cm (3.117 inches)

Connect Speed LED Indicators

Link/Activity LED

Off = No link

Blinking = Activity

Speed LED

Off = 10Mbps

Green = 100Mbps

Amber = 1Gbps

Operating Temperature

Hardware Certifications

0 °C to 55 °C (32 °F to 131 °F) USA: FCC B,

EU: UL CE, Japan: VCCI. Taiwan: BSMI.

Australia/New Zealand: CTICK,

Korea: KCC.

Canada: ICES-003/NMB-003

Aguantia® AQN-108 **Networking Interface RJ-45**

> **System Interface** PCI Express 3 x1

Networking Speeds

Supported

100Mbps, 1Gbps, 2.5Gbps, 5Gbps

Cabling (up to 100m) **Power Consumption**

(active-typical)

Cat5e (or higher) for all speeds 3.5W at 5Gbps, 3.0W at 2.5Gbps

Physical Dimensions

3.72 in x 3.18 in (without bracket)

Technical Specifications - Networking and Communications

Connect Speed LED Indicators

Link/Activity LED

- Off = No link
- Blinking = Activity

Speed LED

- Off = No link
- Amber = <5Gbps
- Green = 5Gbps

0 °C to 55 °C (32 °F to 131 °F)

Operating Temperature

Hardware Certifications USA: FCC B.

> EU: UL CE. Japan: VCCI. Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Intel® X550-T2

Networking Interface

System Interface

Networking Speeds

Supported

Cabling (up to 100m)

2 x RJ-45

PCI Express 3 x4

100Mbps, 1Gbps, 2.5Gbps, 5Gbps, 10Gbps

Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps

Cat6a (or higher) for 10Gbps

Power Consumption (active-typical)

3.9W at 100Mbps 5.5W at 1Gbps 11.2W at 10Gbps

Physical Dimensions

Connect Speed LED

Indicators

Link/Activity LED

Off = No link

Blinking = Activity

5.2 in x 2.7 in (without bracket)

Speed LED

- Off = No link
- Amber = <10Gbps
- Green = 10Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Hardware Certifications

USA: FCC B. EU: UL CE, Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC.

Canada: ICES-003/NMB-003

Intel® X710-DA2 10GBASE-SR Converged **Network Adapter**

Networking Interface System Interface Networking Speeds

Supported

2 SFP+ Ports for LC SFP+ Transceivers

PCI Express 3.0 x8 1Gbps, 10Gbps



Technical Specifications - Networking and Communications

Cabling LC fiber optic cabling with LC SFP+ Transceivers

Power Consumption (active-typical)

4.3W

Physical Dimensions 6.578 in x 2.703 in
Connect Speed LED Link/Activity LED
Indicators • Off = No Ii

Off = No linkBlinking = Activity

Speed LED

Off = 10MbpsGreen = 100MbpsAmber = 1Gbps

Operating Temperature $0 \, ^{\circ}\text{C}$ to 55 $^{\circ}\text{C}$ (32 $^{\circ}\text{F}$ to 131 $^{\circ}\text{F}$)

Hardware Certifications USA: FCC B, EU: UL CE, Japan: VCCI,

Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Note: Windows 7 is NOT supported

10GbE SFP+ SR Connector Type LC
Transceiver Cable Type 62

Cable Type 62.5/125um or 50/125um (core/cladding), graded-index, low metal

content, multimode fiber optic, complying with ITU-T G.651 and ISO/IEC

793-2 Type A1b or A1a, respectively.

Cable Length2-300mWavelength850nmForm FactorSFP+

Physical Dimensions $0.47(h) \times 0.54(w) \times 2.19(d)$ inches

(1.19 x 1.38 x 5.57 cm)

Operating Temperature OC to 45C (32F to 113F) **Operating Humidity** 0% to 85%, noncondensing

Intel® 8265 WLAN Networking Speeds 802.11ac MU-MIMO (up to 867 Mbps)

Bluetooth 4.2

IEEE WLAN Standard IEEE 802.11a/b/g/n/ac, 802.11d, 802.11e, 802.11h, 802.11i, 802.11w;

802.11r, 802.11k, 802.11v pending

Bluetooth 4.2

System Interface PCI Express 2.1 x1

Antenna 2x2

Summary of Changes

SUMMARY OF CHANGES

Date of change:	Version History:		Description of change:
November 1, 2017	From v1 to v2	Added	HP DisplayPort to HDMI Adapter, HP DisplayPort to VGA Adapter, NVIDIA SLI 3-slot Graphics Connector and NVIDIA Quadro Sync II to Graphics section and Microsemi 3152-8i SAS ROC RAID Controller
		Changed	Graphics, Storage / Hard Drives and Memory sections, changed Front and internal view info on the Overview section, changed Operating Systems section, changed System Board section, Physical Security and Serviceability sections
November 29, 2017	From v2 to v3	Added	Processors, hard drives and graphics to offerings, added Declared Noise Emissions information
January 30, 2018	From v3 to v4	Removed	NVIDIA SLI Graphics Connectors from Graphics Cable Adapters section
March 27, 2018	From v4 to v5	Added	Intel Xeon processors added
April 16, 2018	From v5 to v6	Removed	RAID 5
August 13, 2018	From v6 to v7	Added	Footnote to Networking and Communications section
		Changed	Processors section and Operating Systems section
September 4, 2018	From v7 to v8	Removed	HP IEEE 1394b FireWire PCle Card



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